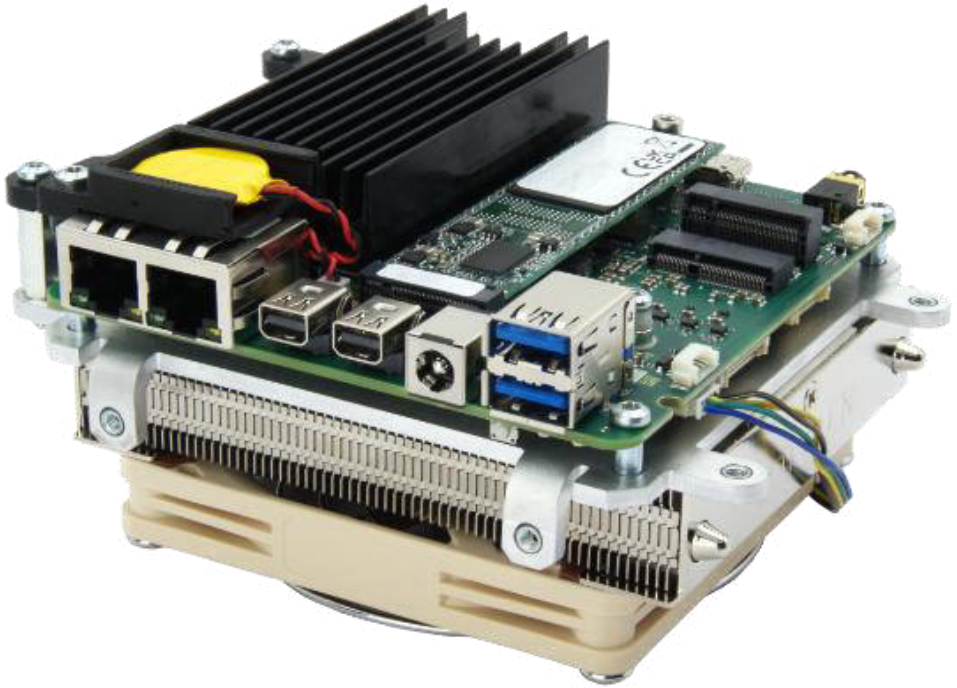
PROFIVE® NUCU “ready to use”
Hardware Reference Manual



Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

E.E.P.D.
...just embedded!

Manufacturer

E.E.P.D. Electronic Equipment Produktion & Distribution GmbH
Gewerbering 3
85258 Weichs

Phone: +49 8136 2282 – 0
Web: https://www.eepd.de
E-Mail: sales@eepd.de

General Notes

This user manual is for your information.

The information contained herein has been checked carefully and is believed to be reliable. However, E.E.P.D. GmbH gives no guarantee or warranty concerning the accuracy of spoken information and shall not be responsible for any loss or damage of any nature resulting from the usage of or from reliance upon it.

We are thankful for all suggestions or improvements at any time.

E.E.P.D. GmbH reserves the right to make changes in the products or specifications, or both, at any time without notice.

08/2026 Version 3.0

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.
08/2026 Version 3.0

E.E.P.D. ...just embedded!

Copyright Notice

Copyright© 2026 E.E.P.D. GmbH. ALL RIGHTS RESERVED!

E.E.P.D. GmbH copyrights this document. You may not reproduce, transmit, transcribe, store in a retrieval system, or translate into any language, in any form or by any means, or otherwise, any part of this publication without the express written permission of E.E.P.D. GmbH.

Trademark Acknowledgement

Intel, Core, Celeron and Atom are registered trademarks of Intel Corporation.

AMD, Ryzen and Radeon are registered trademarks of Advanced Micro Devices, Inc.

Panel Link and TMDS are registered trademarks of Silicon Image, Inc.

VESA is a registered trademark of Video Electronics Standard Association.

Windows 10/11 is a registered trademark of Microsoft Corporation.

PROFIVE® and E.E.P.D.® are registered trademarks of E.E.P.D. Electronic Equipment Produktion and Distribution GmbH.

All rights reserved. All other mentioned trademarks are registered trademarks of their owners.

Disclaimer

This document is provided for the general information of the customer. It describes the general functionality of the board and is not considered as assured characteristics. The written declarations in this specification are not constituent part of any contract.

E.E.P.D. GmbH reserves the right to modify the information contained in this manual as necessary and the customer should ensure that he has the most recent revision of this document.

E.E.P.D. GmbH makes no warranty for the use of its products and bears no responsibility for any errors, which may appear in this document. The customer should be on notice that the field of personal computers is the subject of many patents held by different parties. Customer must ensure that they take appropriate action so that their use of the products does not infringe upon any patents. It is the policy of E.E.P.D. GmbH to respect the valid patent rights of third parties and not to infringe upon or assist others to infringe upon such rights.

E.E.P.D. GmbH assumes no responsibility for circuits, descriptions and tables within this document as far as patents or other rights of third parties are concerned.

Life Support Applications

E.E.P.D. GmbH products are not intended for using as critical components in life support appliances, devices or systems in which the failing of an E.E.P.D. GmbH product could be expected to result in personal injury.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

FCC and CE Disclaimer

This product cannot be used as a stand-alone product!

Therefore, it has to be integrated together with other products like power supplies, mass storage devices (i. e. hard disks), etc. to be functional.

To meet FCC and/or CE requirements every component as well as the combination of all components has to be validated against all standards required for the end product.

In order to meet FCC and/or CE requirements this product has to be integrated into a proper housing, which provides appropriate shielding and insulation.

It is on the customer’s sole responsibility to assure that this end-product meets all required standards.

E.E.P.D. GmbH gives no warranty at all that their products will meet the FCC and CE standards when used in combination with other third-party products or when used in any other way than specified.

Limited Warranty

This product will be free from defects in workmanship and material under normal and proper use for the period of time defined in our General Terms of Business, effective the date of the original shipment from E.E.P.D. GmbH.

In the event of a warranty claim for defects, which appear within the warranty period, customer shall deliver the product along with proof of purchase to the original place of purchase, shipping prepaid. Repair, replacement or refund of the purchase price of the defective product will be at the sole option of the manufacturer. All transportation risks and costs in connection with warranty service are the responsibility of the customer.
THIS WARRANTY IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, INCLUDING WITHOUT LIMITATION, IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE, TO ANY CUSTOMER, CONSUMER, END USER, PURCHASER, OR OTHERWISE. IN NO EVENT SHALL MANUFACTURER BE LIABLE FOR LOSS OF PROFITS, INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES ARISING OUT OF ANY BREACH OF CONTRACT OR WARRANTY, NEGLIGENCE, STRICT LIABILITY OR OTHERWISE.

The remedies for defects in this product are limited to those set forth above. If this limitation of remedies is held by any court to be void or unenforceable, or if no warranty is made, manufacturers liability shall in no event exceed the purchase price of the product giving rise to the claim, regardless of whether such claim is brought in breach of contract or warranty, negligence, strict liability or otherwise.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Product Returns

If you return the product to E.E.P.D. GmbH please remove all connections and peripheral equipment.

Protect the unit through a suitable packaging, preferably use the original packaging.

Packaging

The product is in a protective package to avoid damage during transport.

This protective package should be environmentally friendly recycled after use.

Disposal of Device

At the end of the lifetime please dispose and/or recycle the components of the device accordingly.

Technical Support

For technical information about hardware and software please contact: **support@eepd.de**

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Revision History

Date	Version	Changes	Proofed
19.08.2026	3.0	First release; HW Rev.2/3	

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Table of Contents

General Notes **1**
Revision History **5**
Used Symbols **7**
Product Description **8**
1 Feature Overview **8**
2 Environmental Specification **10**
3 System Overview **11**
4 Assembly **12**
4.1 Product Views 12
4.2 Dimensions 14
5 Feature Details **15**
5.1 Connection Overview 16
5.2 Mini-DP++ Connectors 18
5.3 2.5 Gigabit Ethernet Ports 18
5.4 Dual-USB 3.2 Ports 19
5.5 USB4 Ports 19
5.6 Internal USB 2.0 Connectors 20
5.7 DDR5 SO-DIMM Sockets 20
5.8 Power Connector 21
5.9 M.2 Sockets 22
5.10 OCuLink Connector 23
5.11 Audio Jack 23
5.12 Feature Connector 23
5.13 RS232/485 Connector 24
5.14 Battery Connector and Battery 24
5.15 FAN Connectors 25
5.16 Power Button, Power and SSD Activity LEDs 26
5.17 Power Button Connector 26
6 BIOS **27**
6.1 Entering Setup 27
6.2 Most Common Settings 27
6.3 Main Menu 28
6.4 Advanced Menu 29
6.5 AMD CBS 36
6.6 AMD PBS Menu 42
6.7 Boot Menu 43
6.8 Power Menu 44
6.9 Exit Menu 44
6.10 Security Menu 45
Index of Figures **47**
Index of Tables **49**
Terminology **50**
Classified Index **51**

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Used Symbols

The red danger sign warns you when a wrong or missing action dramatically endangers your life or health. The used components as well as the peripheral components could be destroyed.

The orange warning sign warns you when a wrong or missing action could seriously harm your health or destroy the used components.

The yellow caution sign warns you when a wrong or missing action could damage the component.

The yellow ESD sign draws your attention that static sensitive parts of the component could be destroyed. Unpack shielded components only with ESD protections like an ESD wrist strap.

The information sign gives you more information and advice for optimal use of this product. For example, it helps you to purchase necessary or optional accessories.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Product Description

In the first chapter you will get a glance of all the integrated features. For further information and a brief description of all possible changes and extensions please refer to the corresponding chapter.

1 Feature Overview

Power Supply (see chapter 5.8)

Designed for min. 10.8 V to max. 26.4 V (DC) single power supply, 10 A fused. If 12 V Fan is used input voltage must be min. 13.2 V.

CPU variants with TDP up to 30 W: min. 90 W / recommended 120 W,
CPU variants with TDP up to 54 W: min. 120 W / recommended 150 W.

Current rating of the power supply has to exceed the expected current draw depending on the system configuration, CPU variant and its TDP settings, and peripheral devices used with the system. Power supplies might derate due to lower efficiency at higher operating temperature. Insufficient power supply might lead to the system instability, shutdown and data loss.

Power Connector

2-pin barrel connector for external DC power and ground.

CUI devices power plug ID 2.5 mm, AD 5.5 mm, max. 7 A.

Power Limit

Internal and external 3.3 V power max. 25 W.

Internal and external 5 V power max. 45 W.

Internal and external power is related to m.2 connectors, USB, FAN and display.

Processor Support

AMD Ryzen™ Embedded 8000 series:

8845HS / 8C / 16T / 3.8 GHz – 5.1 GHz / 45 W (35 – 54 W)

8645HS / 6C / 12T / 4.3 GHz – 5.0 GHz / 45 W (35 – 54 W)

8840U / 8C / 16T / 3.3 GHz - 5.1 GHz / 28 W (15 – 30 W)

8640U / 6C / 12T / 3.5 GHz - 4.9 GHz / 28 W (15 – 30 W)

AMD Ryzen™ 8000 series:

8440U / 4C / 8T / 3.3 GHz - 4.7 GHz / 15 W (15 – 30 W)

AMD Ryzen™ PRO 8000 series:

8540U / 6C / 12T / 3.2 GHz – 4.9 GHz / 28 W (15 – 30 W)

Ethernet Controller

2x Intel® i226-V 2.5 Gbit/s Ethernet PCI Express® controllers with IEEE1588, Wake-on-LAN supported by ETH 1. No TSN support.

Other i226 variants on request.

RAM Support*

2x 32 GB dual channel up to DDR5-5600 SO-DIMM memory with ECC support (no ECC with 8440U).

Display

2x Mini-DP++ connector, v1.4, up to 3840 x 2160 @ 60 Hz.

2x USB-C Alt Mode, up to 3840 x 2160 @ 60 Hz at the rear side.

Audio

HDA Codec with MIC IN, stereo headphone OUT on 3.5 mm audio jack.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

USB Support

1x Dual-USB 3.2 Gen2 (10 Gb/s, OCP = 1.5 A each), Type A at the front side.

2x USB4 Gen3x2 (up to 40 Gb/s, OCP = 3 A, together max. 4.5 A) or USB-C Alt Mode, Type C at the rear side.

2x USB 2.0 (480 Mb/s, OCP = 900 mA each) on Molex (PicoBlade) connector.

Storage Support*

1x M.2 Key M, 2280, PCIe Gen4 x4 NVMe.

Expansion Slots

1x Key E, 2230, support for PCIe Gen4 x2 or x1 / USB 2.0, e. g. for WLAN/BT.

1x Key B, 3042, support for PCIe Gen4 x2 / USB 2.0, e. g. for WWAN.

1x OCuLink x4 (SFF-8621 / SFF-9402) connector, PCIe Gen4 x4 interface (3.3 V / 5 V power on request).

Serial Ports

1x RS-232/485 (FDX|HDX) port on internal Molex (PicoBlade) connector.

Cooling

CPU fan, 12 V, max. 250 mA, not fused.

Optional auxiliary fan, 12 V, max. 250 mA, not fused.

OS Support

Microsoft® Windows® 11

Microsoft® Windows® 11 IoT Enterprise

Linux Ubuntu 24.04 LTS

Extended Features

Onboard µ-Controller-IC for:

- Input voltage level detection
- Power-up sequencing and timing
- System reset management
- Temperature monitoring, fan control and watchdog
- Power button input

Feature connector (4x GPIO [3.3 V], max. 3x GPO [open drain/50 kHz], not fused)

Power and status LEDs

Power button onboard

Power button connector

RTC battery connector

AMD firmware Trusted Platform Module

TPM 2.0 support (Infineon SLB 9670)

Mounting: stand-alone

Size approx. 131 x 108 x 61 mm

Weight approx. 710 g + options

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

*It is recommended to use SSDs with built-in heatsinks as well as additional memory cooling to ensure optimal thermal conditions.

Cooling solution for subsequent installation by the customer:
Ordering number: KIUKKRAM1

Factory assembled cooling solution:
Ordering number: KIUKKRAM2

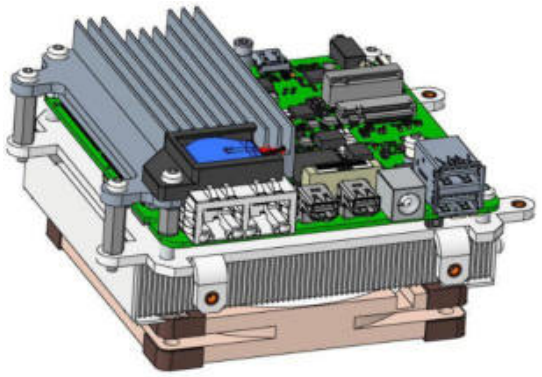


Fig. 1: NUCU with additional memory cooling

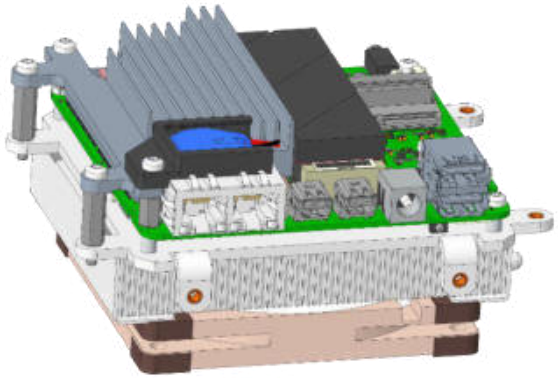


Fig. 2: NUCU with additional memory and SSD cooling

2 Environmental Specification

Max. Operating Temperature

0 °C to +60 °C ambient commercial grade.

Adequate cooling provided, depending on variant and cooling system.

CPU throttling may occur at higher ambient temperatures.

Max. Storage Temperature

-40 °C to +85 °C, non-condensing.

Max. rel. Humidity for all versions

95 % @ 40 °C non-condensing while stored, 89% while working.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

3 System Overview

This chapter describes the main hardware components of the NUCUX board.

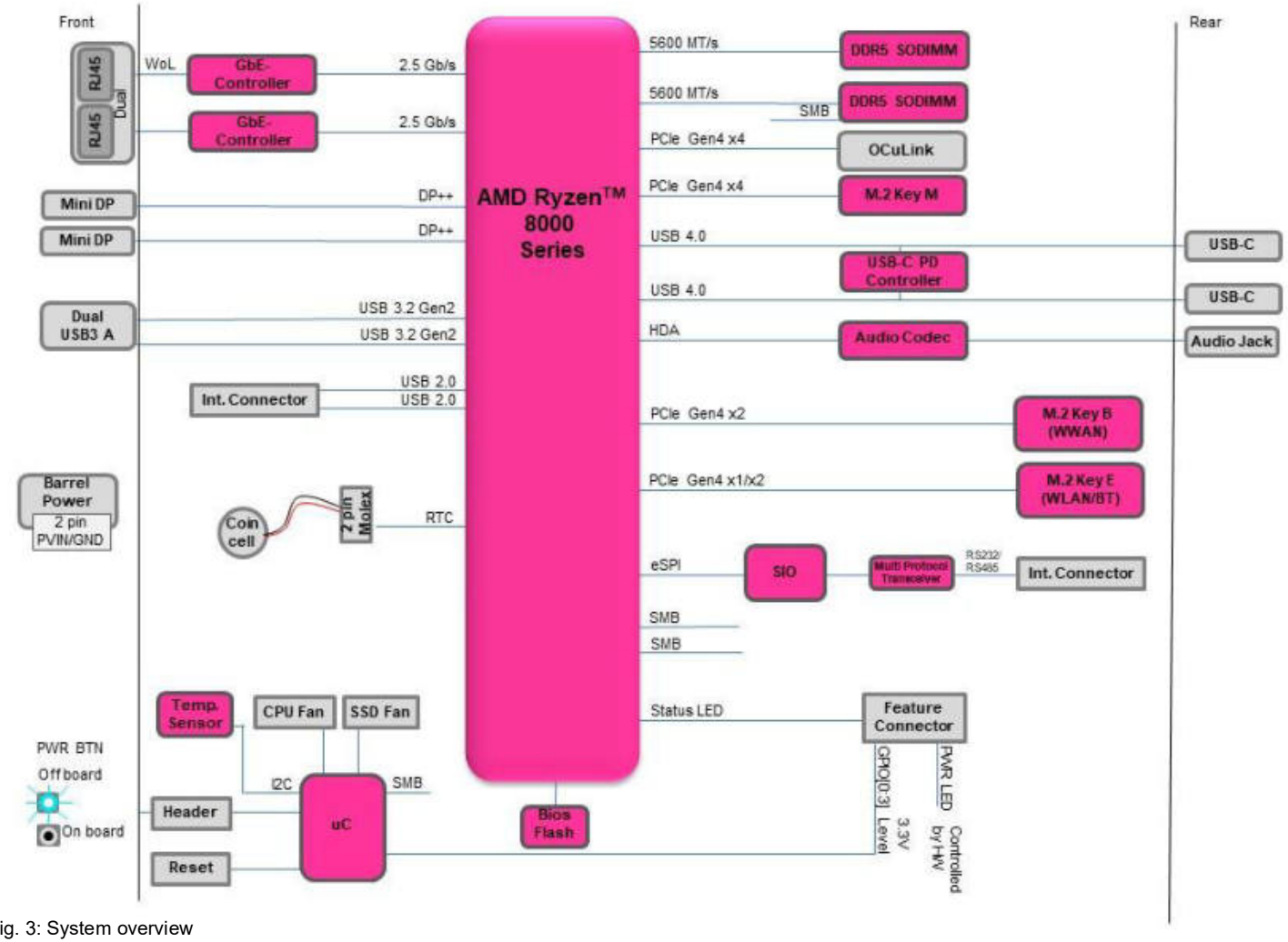


Fig. 3: System overview

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

4 Assembly

The NUCU “ready to use” is designed as stand-alone product. Do not disassemble the cooling solution, this will void the warranty.
The illustration shows an example of a variant with active cooling (Noctua NH-L9a-AM4).

4.1 Product Views

Top View

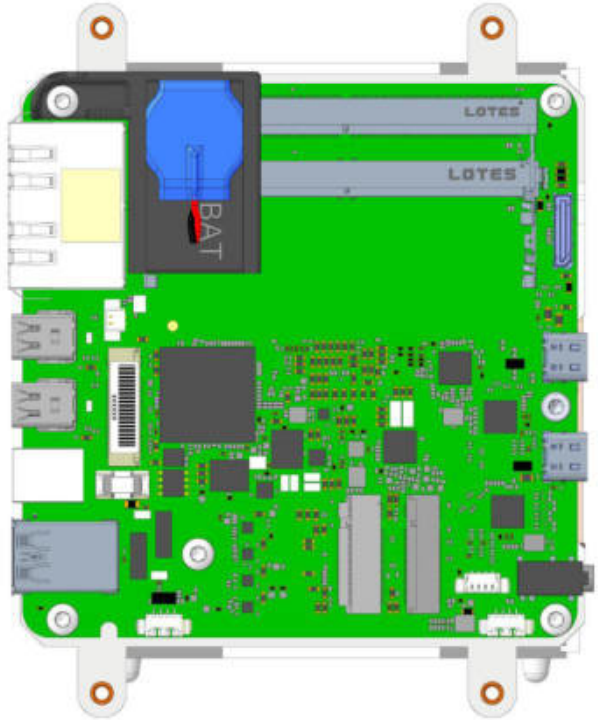


Fig. 4: Top view

Bottom View

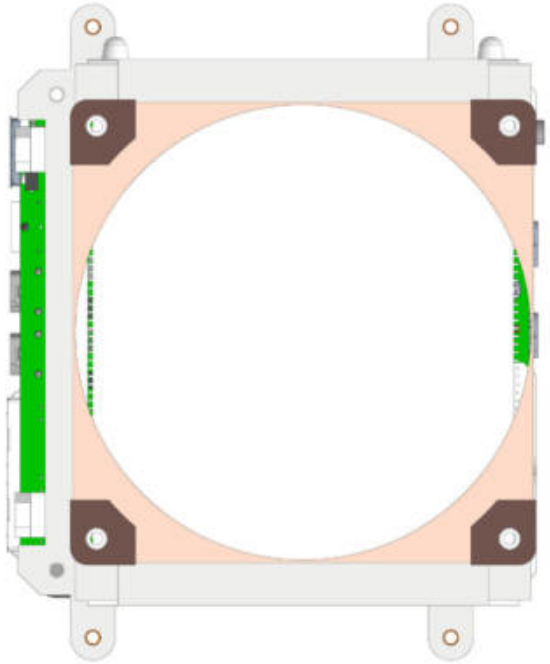


Fig. 5: Bottom view

Side View

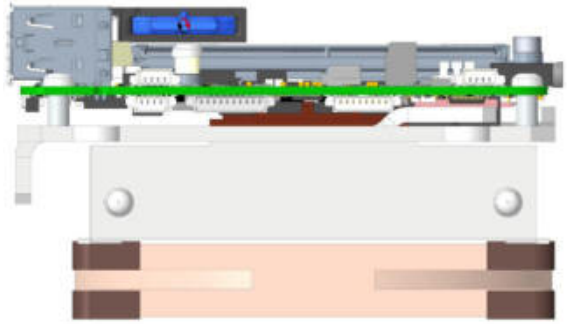


Fig. 6: Side view

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Front View

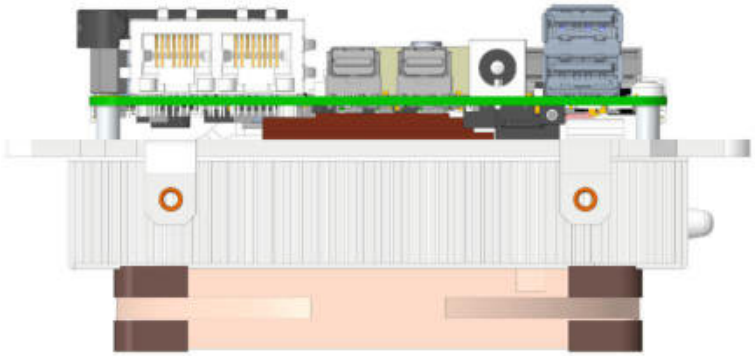


Fig. 7: Front view

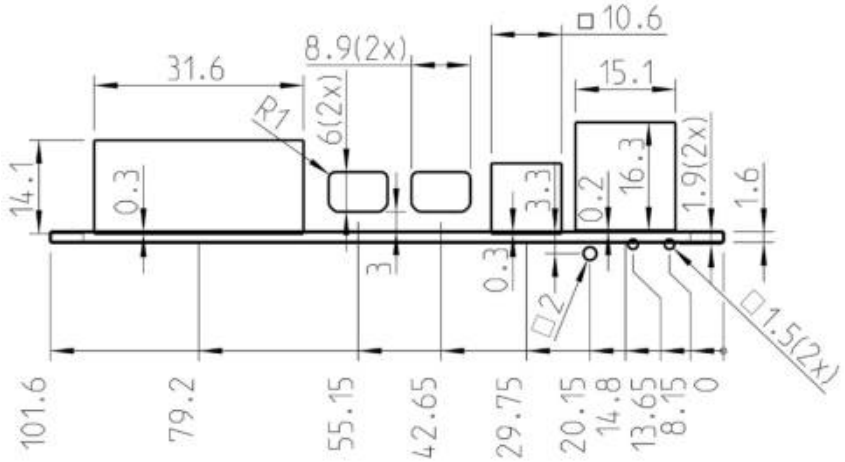


Fig. 8: Recommended cutouts front panel, values [mm]

Rear View

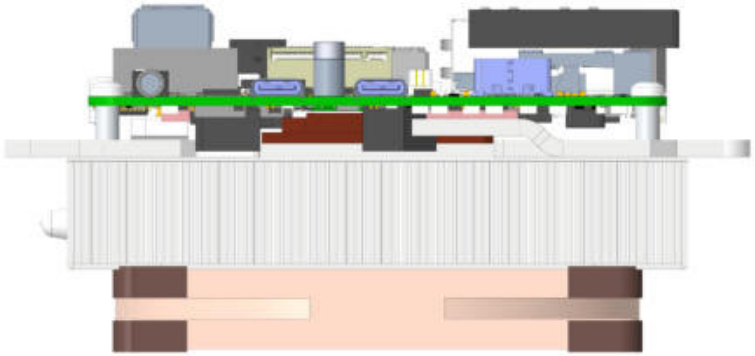


Fig. 9: Rear view

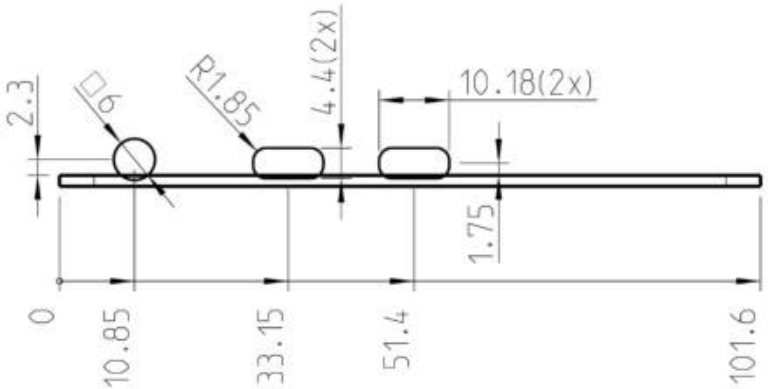


Fig. 10: Recommended cutouts rear panel, values [mm]

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

4.2 Dimensions

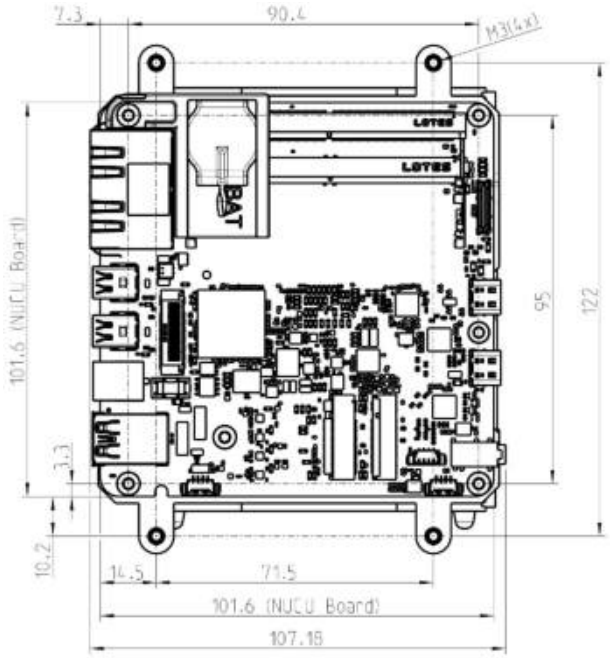


Fig. 11: Dimensions top side, values [mm]

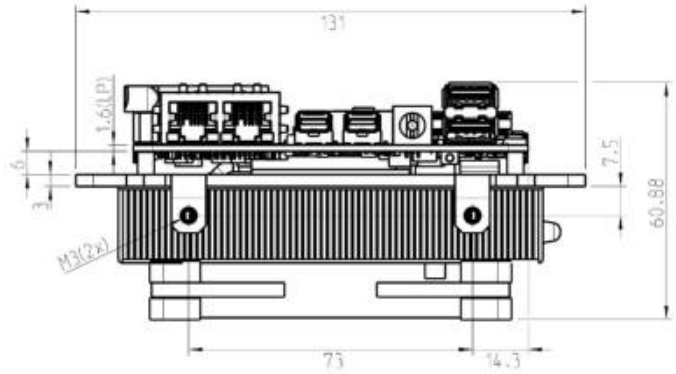


Fig. 12: Dimensions front side, values [mm]

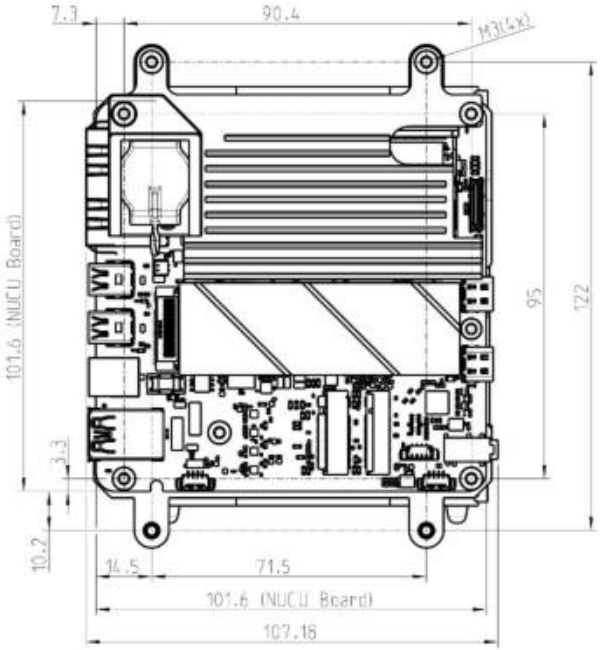


Fig. 13: Dimensions top side with additional cooling, values [mm]

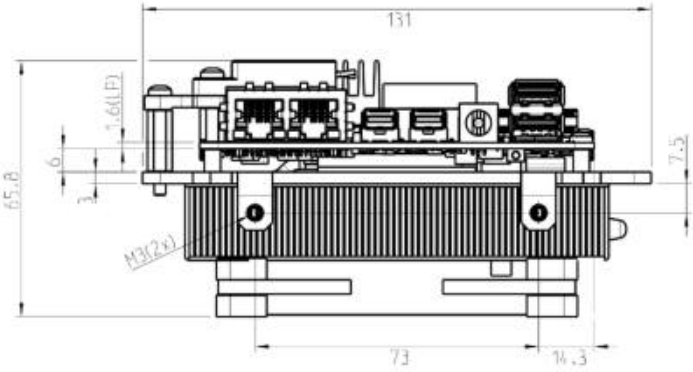


Fig. 14: Dimensions front side with additional cooling, values [mm]

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5 Feature Details

The following schedule contains all the necessary information to connect the board to your peripheral equipment.

On the left side of the page, you will see the position on the board (red mark) and on the right side a magnified image of the explained item.

The explanation provides general information, electrical specifications and a pin assignment table.

All voltages are DC:	
VCC	5 V +/- 5%
P3V3	3.3 V +/- 5%
P12V_FAN	12 V +/- 5%
PVIN (min. – max.)	10.8 – 26.4 V
VDD_FAN	12 V +/- 5%

Tab. 1: Voltage overview

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.1 Connection Overview

Top Side

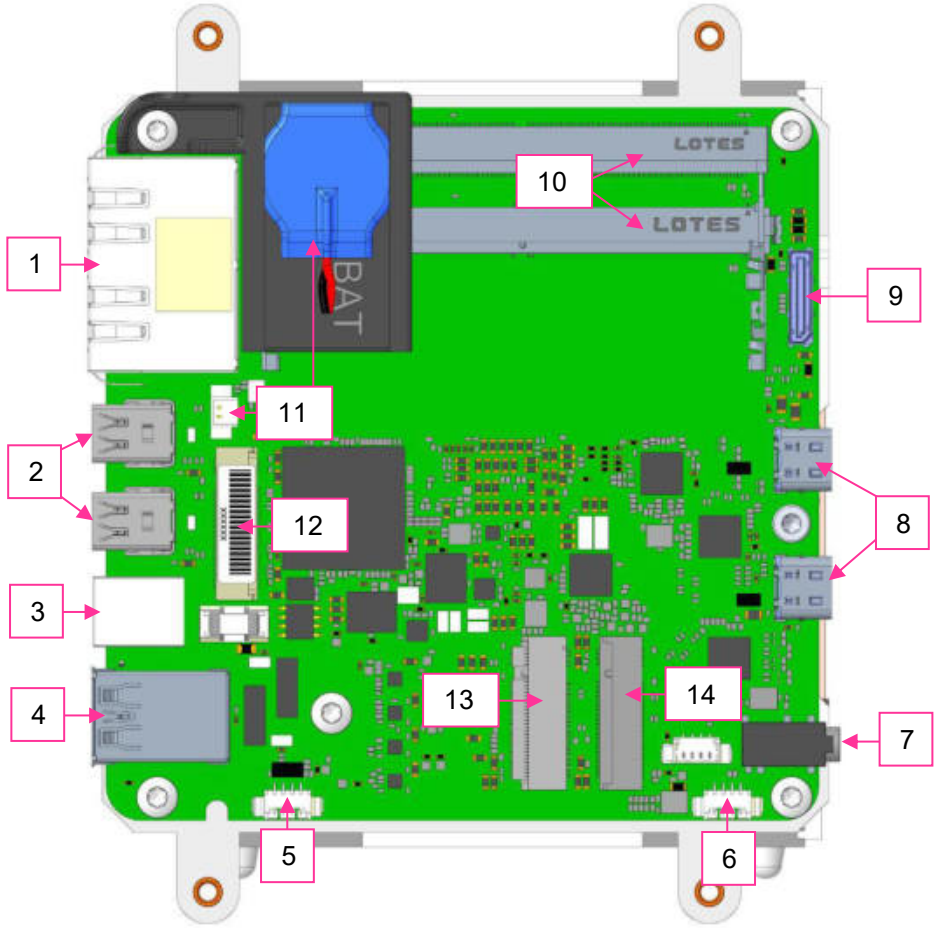


Fig. 15: Connection overview top side

1 – 2.5 Gigabit Ethernet ports, see chapter *5.3*
2 – Mini Display port, see chapter *5.2*
3 – Power connector, see chapter *5.8*
4 – Dual-USB, see chapter *5.4*
5 – Auxiliary fan connector, see chapter *5.15*
6 – Power button connector, see chapter *5.17*
7 – Audio jack, see chapter *5.11*
8 – USB-C 4.0 ports, see chapter *5.5*
9 – OCuLink connector, see chapter *5.10*
10 – DDR5 SO-DIMM sockets, see chapter *5.7*
11 – Battery connector and battery, see chapter *5.14*
12 – M.2 Key M socket, see chapter *5.9*
13 – M.2 Key E socket, see chapter *5.9*
14 – M.2 Key B socket, see chapter *5.9*

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Bottom Side

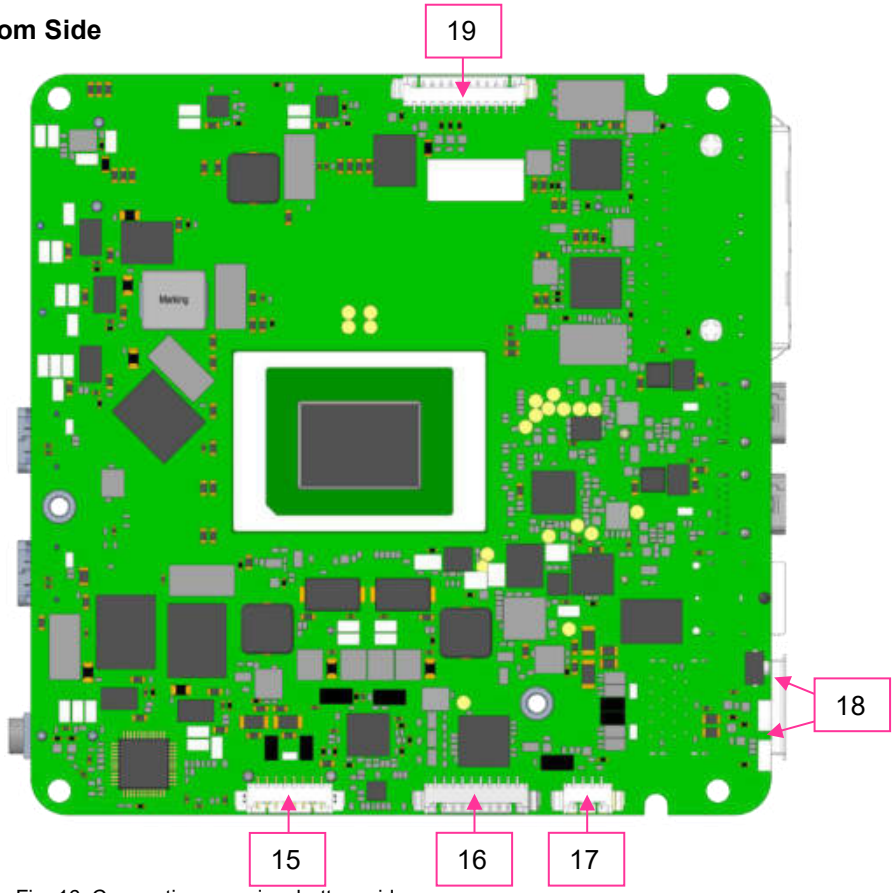


Fig. 16: Connection overview bottom side

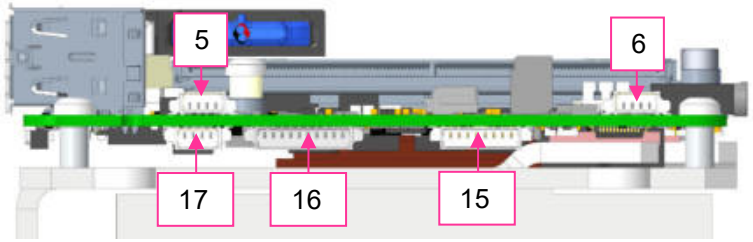


Fig. 17: Connection overview side

15 – internal USB 2.0 connector, see chapter *5.6*

16 – RS22/485 connector, see chapter *5.13*

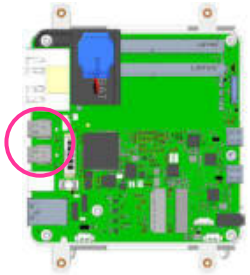
17 – CPU fan connector, see chapter *5.15*

18 – Power button, Power and SSD Activity LEDs, see chapter *5.16*

19 – Feature connector, see chapter *5.12*

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.2 Mini-DP++ Connectors



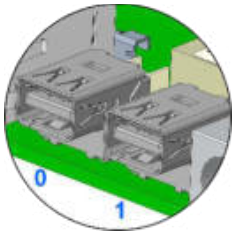


Fig. 18: Mini-DP++ connectors detail

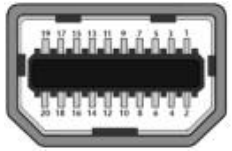


Fig. 19: Mini-DP++ connector schematic

CAUTION

Important Note:

There are two types of DisplayPort cables:

If you connect the display directly to the Mini DP, please use cable with Pin 20 not connected.

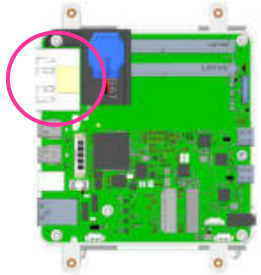
If you use active cables/adapters (e.g. Mini DP to DP, Mini DP to HDMI), please use cable with Pin 20 (supply voltage) on both ends that are connected.

Possible effects if wrong cable is used:

System might not start up properly.
Dongle does not work properly (black display).

5.3 2.5 Gigabit Ethernet Ports

The Dual-Ethernet socket uses two Intel® i226 controllers.
Ethernet port 1 supports Wake-on-LAN.



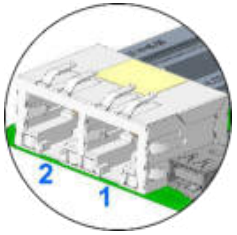


Fig. 20: Ethernet Dual-port detail

Yellow LED
Speed-LED is on during 2.5 and 1 Gbit transmission and switched off during 10/100 Mb/s transmission.

Green LED
Link-/Activity-LED is permanently on to indicate an active connection on the Ethernet port. LED blinks during communication with the Ethernet network.

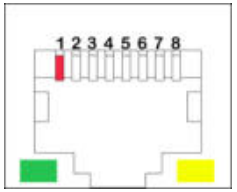


Fig. 21: Ethernet port schematic

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.4 Dual-USB 3.2 Ports

USB 3.2 type A ports providing max. 1.5 A per port (OCP).
Support for USB 2.0 and USB 3.2 Gen1/Gen2 (up to 10 Gb/s).

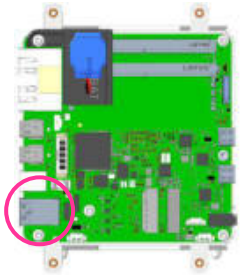


Fig. 22: Dual-USB-A 3.2 port detail

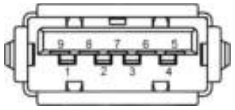
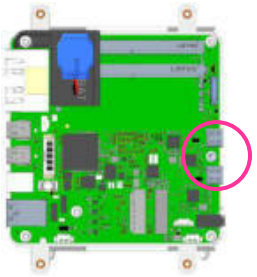


Fig. 23: USB-A 3.2 port schematic

5.5 USB4 Ports

USB4 Gen3x2 (40 Gb/s) type C ports providing max. 3 A (OCP) per port, together max. 4.5 A.



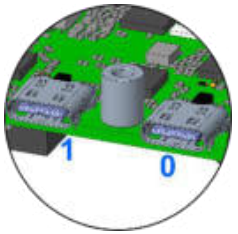


Fig. 24: USB-C ports detail

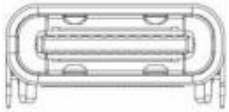
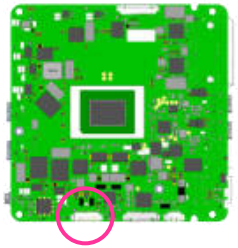


Fig. 25: USB-C port schematic

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.6 Internal USB 2.0 Connectors

USB 2.0 (480 Mb/s) internal connectors providing max. 900 mA (OCP).



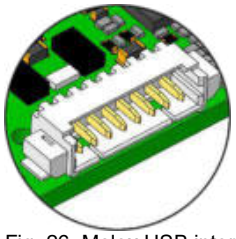


Fig. 26: Molex USB internal connector detail

Counterpart – plug:

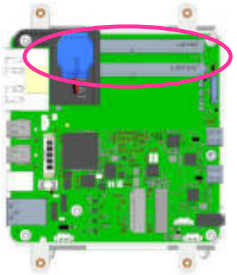
MOLEX Pico Blade
0510210900

Fig. 27: Molex USB internal connector schematic

Pin	Signal
1	VCC_USB2_6 → 5V +/- 5%, OCP = 900 mA
2	USB2_6_N
3	USB2_6_P
4	GND
5	VCC_USB2_7 → 5V +/-5%, OCP = 900 mA
6	USB2_7_N
7	USB2_7_P
8	GND

Tab. 2: USB internal connector

5.7 DDR5 SO-DIMM Sockets



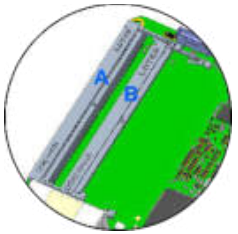


Fig. 28: DDR5 SO-DIMM sockets detail

Use only DDR5 SO-DIMM modules compliant with the DDR5 Standard.
Dual channel DDR5 SO-DIMM memory, max. 2x 32 GB, up to 5600 MT/s, with ECC support.

Assembly:

First slide RAM module into the RAM socket.
Then press the module in direction to the board till you hear it snap.

Disassembly:

First press both clamps outwards.
Then the RAM module will set upright automatically.
Remove the module from the socket.

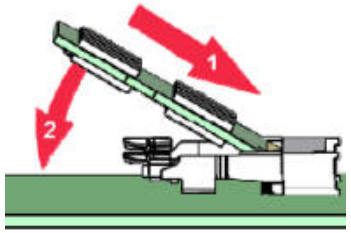


Fig. 29: RAM assembly

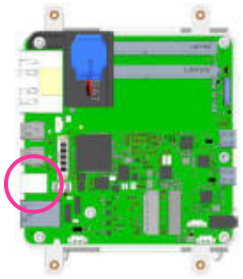
Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.8 Power Connector

CAUTION

For a safe and stable operation, the following criteria of the power supply must be met:

The external power supply must meet the UL/IEC 62368-1 for PS2 and LPS. The PROFIVE® NUCU board is designed to be powered by a 100W Class 2 (ES2/PS2) power supply with a minimum of 120W peak power according to the UL/IEC 62368-1 standard.
Power source must be capable to respond to fast load changes!
Supply voltage (PVIN) min. 10.8 V / max. 26.4 V (DC).
The dimensioning of the power cable wires must be sufficient – according to the maximum electrical specifications on the product label – in accordance with the provisions of the standards EN 62368-1, VDE 0100, EN 60204 or UL 61010-1.



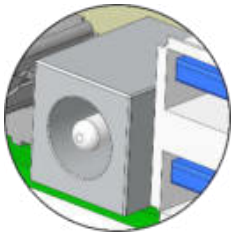


Fig. 30: Power connector detail

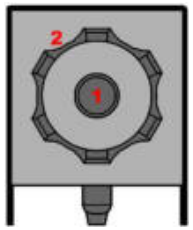


Fig. 31: Power connector schematic

Counterpart – plug:

CUI Devices Power Plug ID 2.5 mm, AD 5.5 mm, max. 7A

Ordering number: PP3-002B

Pin	Signal
1	PVIN
2	GND

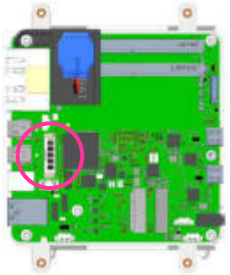
Tab. 3: Power connector

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.9 M.2 Sockets

M.2 Socket Key M

2280, PCIe Gen4 x4 NVMe, P3V3 max. 3.5 A, not fused



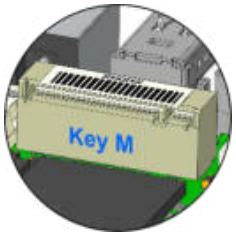
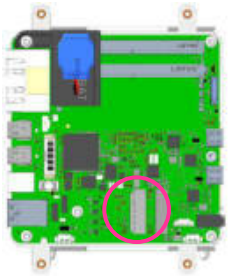


Fig. 32: M.2 Key M connector detail

M.2 Socket Key E

2230, PCIe Gen4 x1 or x2 and USB 2.0, P3V3 max. 2 A, not fused



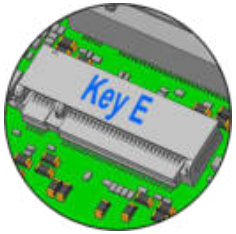
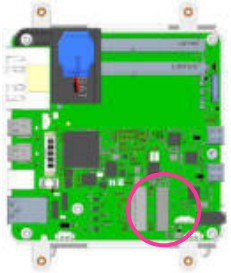


Fig. 33: M.2 Key E connector detail

M.2 Socket Key B

3042, PCIe Gen4 x2 and USB 2.0, P3V3 max. 2.5 A, not fused



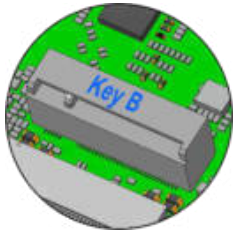


Fig. 34: M.2 Key B connector detail

Installing M.2 modules

Insert the M.2 module into the corresponding slot at an angle. Press it down on the side that protrudes and secure it with the screw provided.

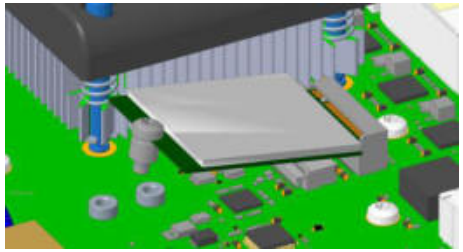


Fig. 35: M.2 module assembly example

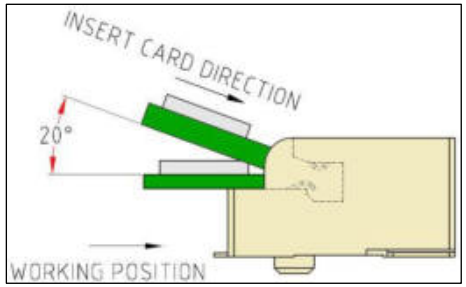
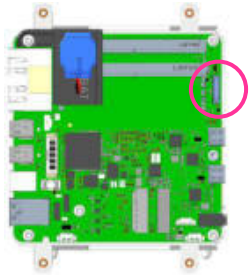


Fig. 36: M.2 module assembly angle

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.10 OCuLink Connector



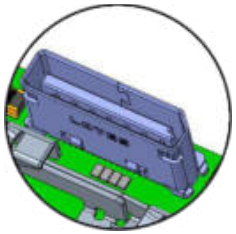


Fig. 37: OCuLink connector detail

Counterpart – plug:

OCuLink cable SFF-8611

5.11 Audio Jack

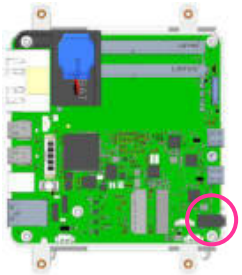


Fig. 38: Audio Jack detail

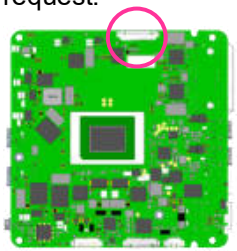
CAUTION

For optimum audio performance:

Please ensure to use cables provided by E.E.P.D.

5.12 Feature Connector

This feature requires Linux driver or Windows Library for OEM customers on request.



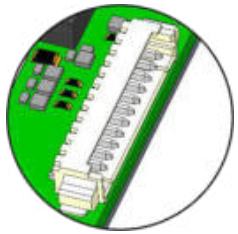


Fig. 39: Molex feature connector detail

Counterpart – plug:

MOLEX Pico Blade
0510211200

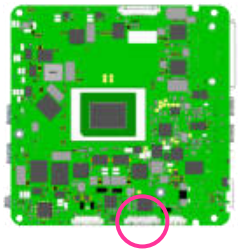
Fig. 40: Molex feature connector schematic

Pin	Signal	
1	3.3 V +/- 5% | 200 mA max.| not fused	
2	P12V_FAN: 12 V +/-5% | 250 mA max. | not fused	
3	GPIO0	max. 3.3 V / max. 15 mA sink/source
4	GPIO1	
5	GPIO2	
6	GPIO3	
7	GPO4	PWM open drain outputs with 100 Ω series resistor. I_{sink} max. = 25 mA
8	GPO5	
9	GPO6	
10	STATUS_LED_ANODE 3.3 V +/- 5% with 100 Ω series resistor (1/16W), 33 mA max., not fused	
11	STATUS_LED_CATHODE	
12	GND	

Tab. 4: Feature connector

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.13 RS232/485 Connector



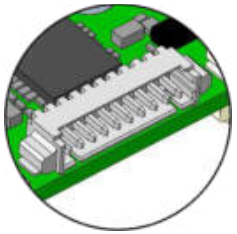


Fig. 41: Molex RS232/485 connector detail

Counterpart – plug:

MOLEX Pico Blade
0510211000

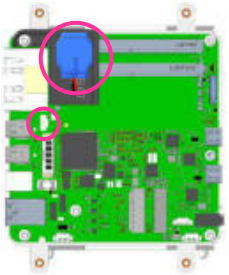
Fig. 42: Molex RS232/485 connector schematic

Pin	Signal RS232*	Signal RS485/FDX*	Signal RS485/HDX for Windows 10/11 only*
1	DCD	RS485-TX_N	RS485-RX/TX_N
2	DSR	-	-
3	RXD	RS485-TX_P	RS485-RX/TX_P
4	RTS	-	-
5	TXD	RS485-RX_P	-
6	CTS	-	-
7	DTR	RS485-RX_N	-
8	-	-	-
9	VCC 5 V +/-5%, max. 500 mA not fused	VCC 5 V +/-5%, max. 500 mA not fused	VCC 5 V +/-5%, max. 500 mA not fused
10	GND	GND	GND

Tab. 5: RS232/485 connector

*See BIOS setting chapter 6.4.7.1 UART Port 1/2 Configuration

5.14 Battery Connector and Battery



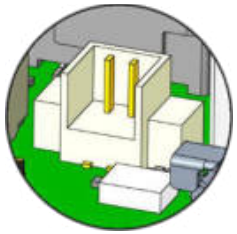


Fig. 43: Molex battery connector detail

Counterpart – plug:

MOLEX Pico Blade
0510210200

Battery with cable ordering number:
W-BATCR1A

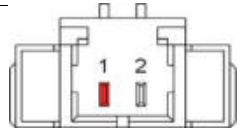


Fig. 44: Molex battery connector schematic

Pin	Signal
1	BATT
2	GND

Tab. 6: Battery connector

WARNING

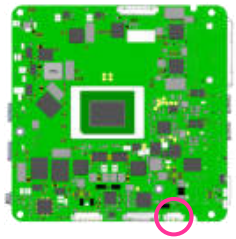
Danger of explosion if battery is incorrectly replaced.

Use only Lithium cell assemblies from EEPD. Battery assemblies can be obtained through sales@eepd.de.
For proper function of the board change the battery every five years.

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.15 FAN Connectors

CPU FAN



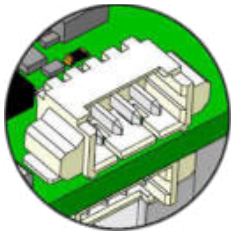


Fig. 45: Molex CPU FAN connector detail

Counterpart – plug:

MOLEX Pico Blade
0510210400

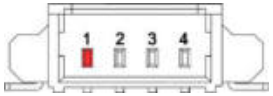
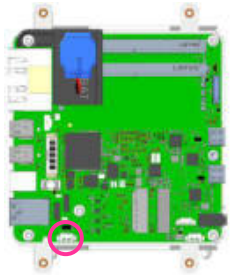


Fig. 47: Molex FAN connector schematic

Pin	Signal
1	GND
2	VDD_FAN 12V +/- 5% | max. 250 mA | not fused
3	FAN_TACHO
4	FAN_PWM

Tab. 7: FAN connectors

Auxiliary FAN (e. g. for SSD)



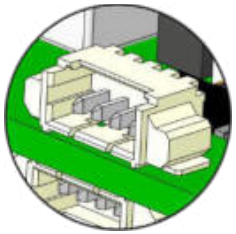


Fig. 46: Molex auxiliary FAN connector detail

CAUTION

An incorrectly connected fan can cause damage to the fan and the board!

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

5.16 Power Button, Power and SSD Activity LEDs

Press power button once to start up.
Press power button to shut down into S3/S4/S5 (Standby/Hibernate/OFF; depending on OS setting).
Hold power button (> 4 sec.) for hard shut down into S5 (OFF). May result in data loss.

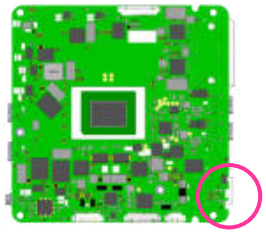


Fig. 48: Power Button/Power and SSD Activity LEDs detail

5.17 Power Button Connector

Press power button once to start up.
Press power button to shut down into S3/S4/S5 (Standby/Hibernate/OFF; depending on OS setting).
Hold power button (> 4 sec.) for hard shut down into S5 (OFF). May result in data loss.

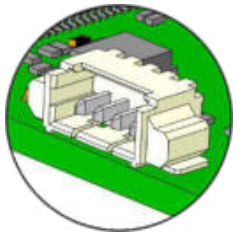


Fig. 49: Molex power button connector detail

Counterpart – plug:

MOLEX Pico Blade
0510210400

Fig. 50: Molex power button connector schematic

Pin	Signal
1	PWR_LED_ANODE 3.3V +/- 5% with 100 Ω series resistor | max. 33 mA, not fused
2	PWR_LED_CATHODE
3	GND
4	POWERBUTTON

Tab. 8: Power button connector

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6 BIOS

The following description shows a snapshot of the BIOS setup. Later BIOS updates may change the content slightly.

Asterisk (*) indicates default setting.

6.1 Entering Setup

Power on the board and press and hold [ESC] immediately to enter Setup.

6.2 Most Common Settings

- Firmware / BIOS Version:
  Setup Utility → Main (chapter *6.3*)
  or Setup Utility → AMD PBS → AMD Firmware Version (chapter *6.6.1*)

- Boot / PXE Boot:
  Boot Manager
  or Setup Utility → Boot (chapter *6.7*)

- TDP, fan control, boost mode:
  TDP setting (chapter *6.5.5*):
  Setup Utility → AMD CBS → SMU Common Options → System Configuration

  Fan control (chapter *6.5.5.1*):
  Setup Utility → AMD CBS → SMU Common Options → CPU and Auxiliary Fan Control

  Boost mode (chapter *6.5.1*):
  Setup Utility → AMD CBS → CPU Common Options → Core Performance Boost

- Change shared graphics memory (chapter *6.5.2.1*):
  Setup Utility → AMD CBS → NBIO Common Options → GFX Configurations → UMA Frame Buffer Size

- USB power
  USB Power off in S5 (chapter *6.4.6*):
  Setup Utility → Advanced → NUCU Options → USB Power off in S5
  or
  USB VCC control (chapter *6.4.3.1*):
  Setup Utility → Advanced → USB Configuration

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.3 Main Menu

Once you enter the Setup Utility, the Main Menu will appear on the screen:

Fig. 51: Main menu

This setup menu shows an overview of board configuration, CPU type, memory and firmware revisions.

BIOS Settings	Options	Description
System Time	No options	Set the time. Use Tab to switch between time elements [hour:min:sec]. Valid range is from 0 to 23, 0 to 59, 0 to 59. INCREASE/REDUCE: +/-.
System Date	No options	Set the date. Use Tab to switch between date elements [month/day/year]. Valid range is from 1 to 12, 1 to 31, 2000 to 2099. (Error checking will be done against month/day/year combinations that are not supported.) INCREASE/REDUCE: +/-.
About this Software		

Tab. 9: Main menu

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4 Advanced Menu

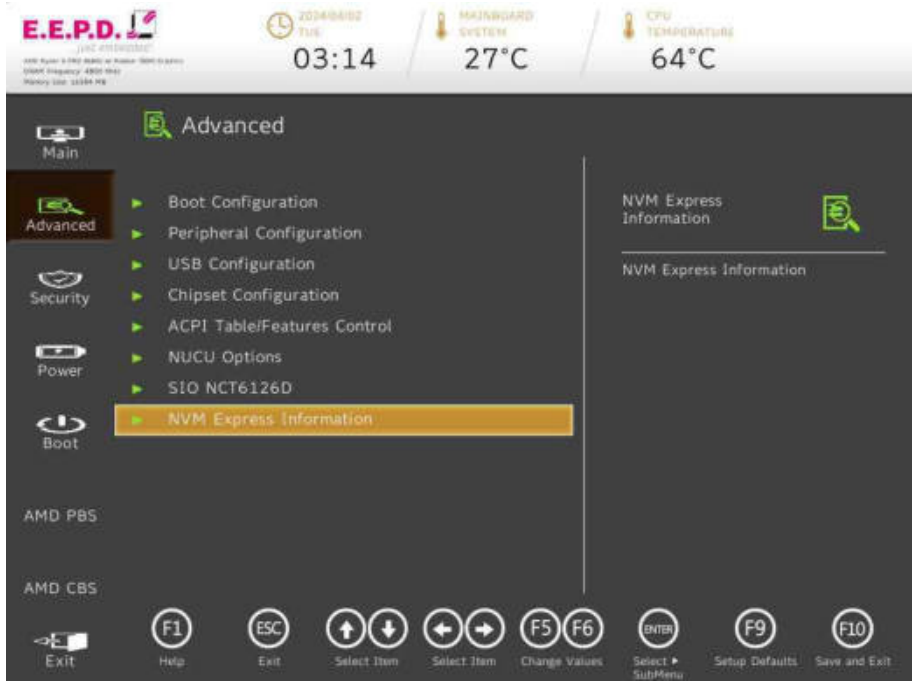


Fig. 52: Advanced menu

BIOS Settings	Options	Description
Boot Configuration	See submenu	Configures Boot Settings.
Peripheral Configuration	See submenu	Configures the peripheral devices.
USB Configuration	See submenu	Configure the USB support
Chipset Configuration	See submenu	Advanced Chipset Configuration Options.
ACPI Table/Features Control	See submenu	Configures ACPI Tables/Features setting.
NUCU Options	See submenu	Configure: PIC Watchdog, Wake on LAN, Power & Effect LED, USB Power off in S5
SIO NCT6126D	See submenu	SIO NCT6126D configuration menu
NVMe Information	See submenu	This function shows the connected NVMe devices.

Tab. 10: Advanced menu

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.1 Boot Configuration

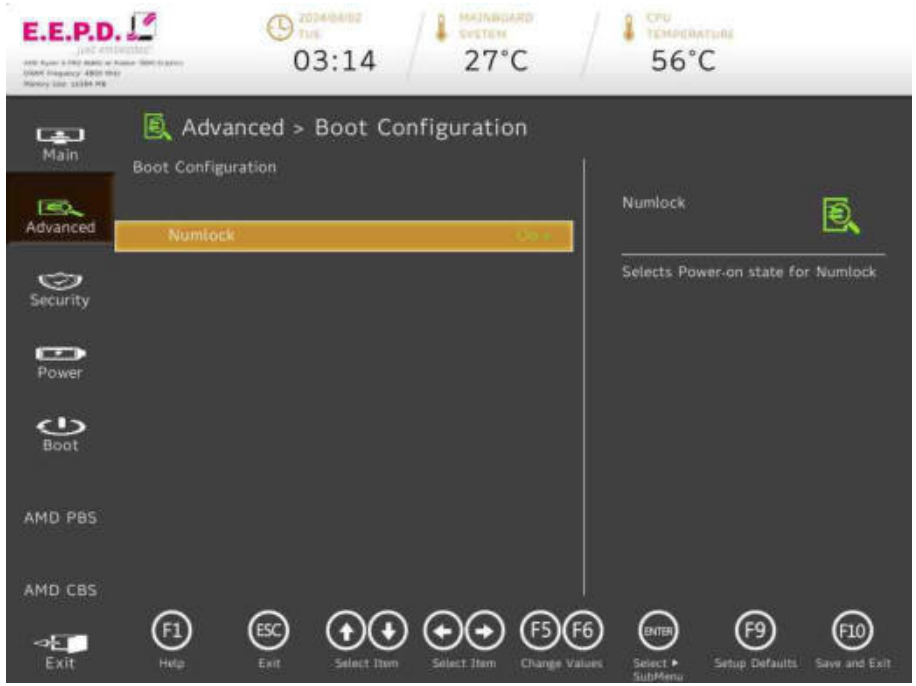


Fig. 53: Boot configuration

BIOS Settings	Options	Description
Numlock	<Off> <On>*	Configuration of Numlock key at power up.

Tab. 11: Boot configuration

6.4.2 Peripheral Configuration

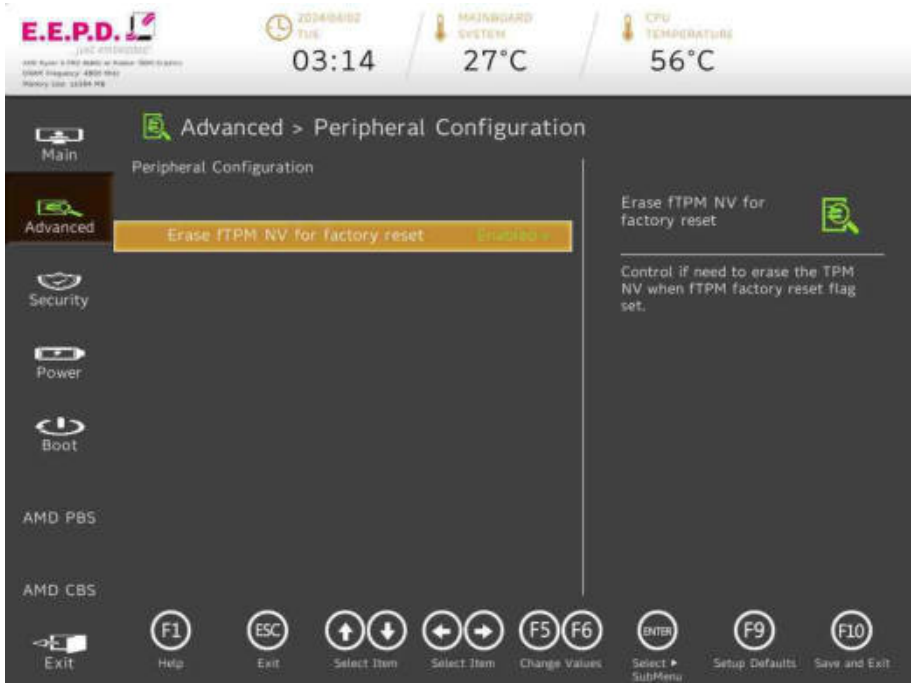


Fig. 54: Peripheral configuration

BIOS Settings	Options	Description
Erase fTPM NV for factory reset	<Disabled> <Enabled>*	Control if need to erase the TPM NV when fTPM factory reset flag set.

Tab. 12: Peripheral configuration

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.3 USB Configuration

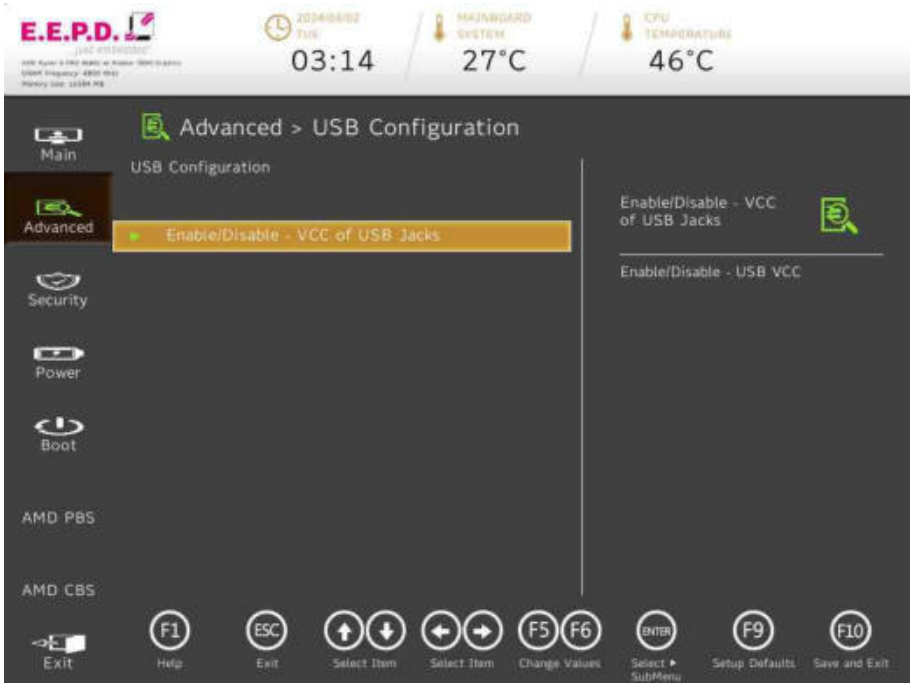


Fig. 55: USB configuration

BIOS Settings	Options	Description
Enable/Disable – VCC of USB Jacks	See submenu	Enable/Disable – USB VCC

Tab. 13: USB configuration

Note:
In order to not exclude yourself from the BIOS setup, at least one USB port should be enabled at all times.

6.4.3.1 Enable/Disable – VCC of USB Jacks

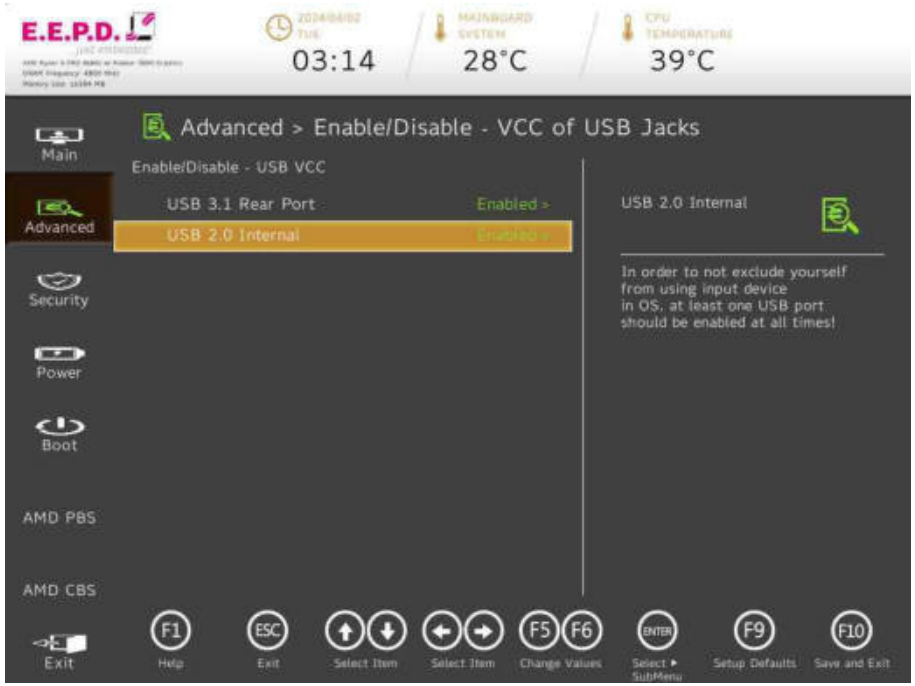


Fig. 56: USB ports

BIOS Settings	Options	Description
USB 3.1 Rear Port	<Disabled> <Enabled>*	This function allows you to enable or disable the power for the Rear USB port.
USB 2.0 Internal	<Disabled> <Enabled>*	This function allows you to enable or disable the power for the internal USB port.

Tab. 14: USB ports

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.4 Chipset Configuration

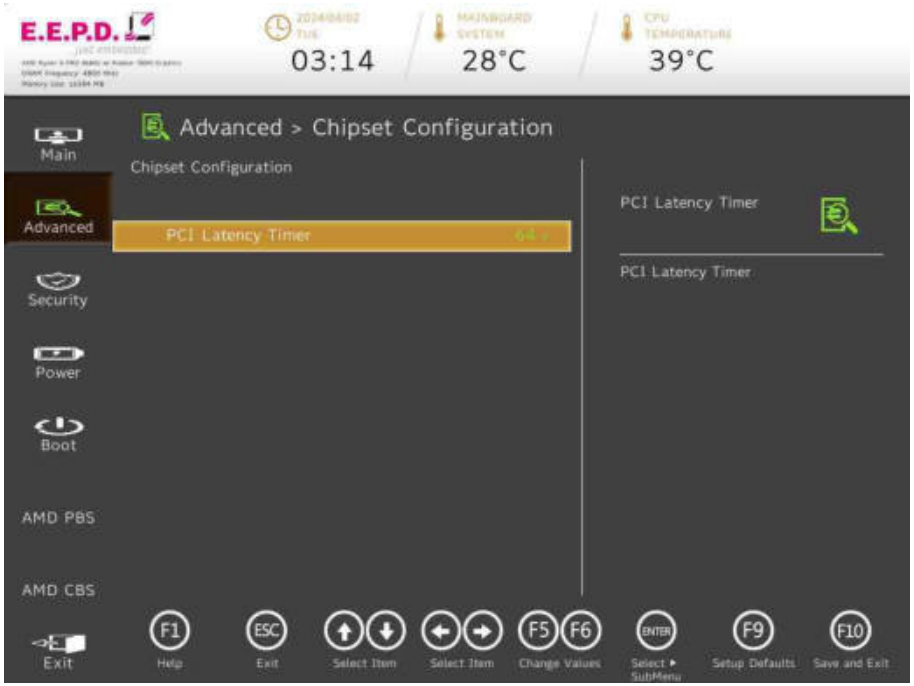


Fig. 57: Chipset configuration

BIOS Settings	Options	Description
PCI Latency Timer	<32> <64>* <96> <128> <160> <192> <224> <248>	PCI Latency Timer

Tab. 15: Chipset configuration

6.4.5 ACPI Table/Features Control

Fig. 58: ACPI table

BIOS Settings	Options	Description
HPET - HPET Support	<Disabled> <Enabled>*	High Precision Event Timer is supported in Windows Vista or above. HPET controller should not been seen in Windows XP no matter enable/disable in SCU. If this feature is enabled, the HPET table will be added into ACPI Tables.

Tab. 16: ACPI table

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.6 NUCU Options

Fig. 59: NUCU options

CAUTION

Enabling watchdog leads to the reset of the board after time out. Please contact EEPD for further instructions.

BIOS Settings	Options	Description
PIC Watchdog	<Disabled>* <Enabled>	Enable/Disable the PIC watchdog
Watchdog Timeout (s)	Adjust value [30-254] Default value [40]*	Seconds before PIC watchdog times out. Range 30-254 seconds.
Wake on LAN	<Disabled> <Enabled>*	Enable/Disable Wake on LAN
Power LED Mode	<Disabled> <Enabled>*	Set Power LED Mode (Enable/Disable)
EFFECT-RGB-LED	<Disabled>* <Enabled>	Set GPO [4:6] LED Mode: Enabled = Temperature dependent RGB-LED for Indication of heat Disabled = normal GPO function
USB 3.1 Rear Port	<Disabled>* <Enabled>	Force USB VCC Off in S5. [Disabled]: Leaves VCC of USB Jack unchanged as in Advanced > USB Configuration > Enable/Disable - VCC of USB Jacks [Enabled]: Switches USB VCC off in S5 (System Power Off)!
USB 2.0 Internal	<Disabled>* <Enabled>	

Tab. 17: NUCU options

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.7 SIO NCT6126D

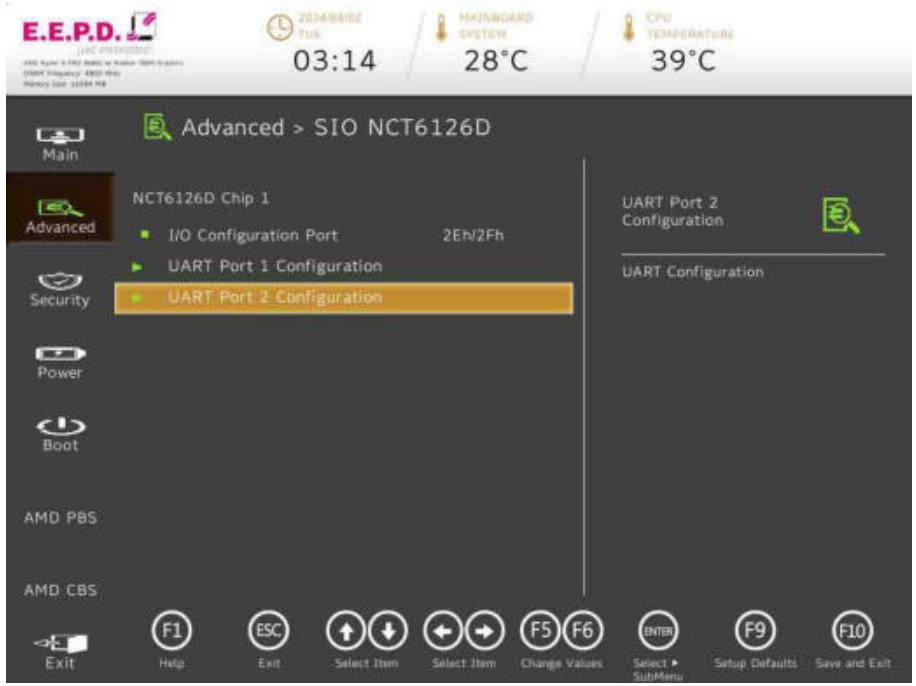


Fig. 60: SIO NCT6126D

BIOS Settings	Options	Description
UART Port 1 Configuration	See submenu	UART Configuration
UART Port 2 Configuration	See submenu	UART Configuration

Tab. 18: SIO NCT6126D

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.7.1 UART Port 1/2 Configuration

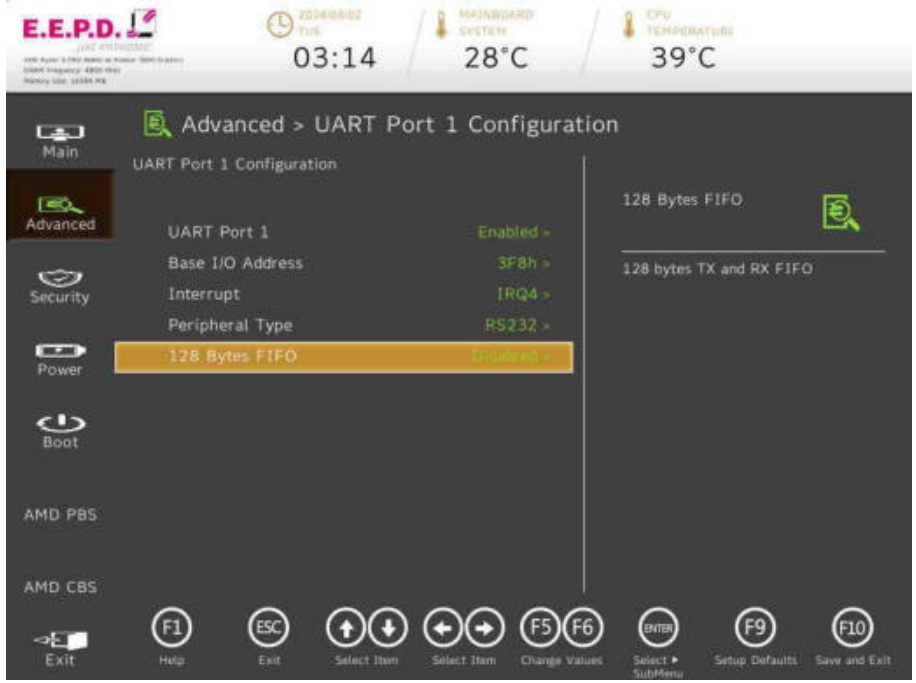


Fig. 61: UART port 1/2 configuration

BIOS Settings	Options	Description
UART Port 1/2	<Disabled> <Enabled>*	Configure UART port 1/2 using options: [Disabled] Disable device [Enabled] Enable device and use below settings
Base I/O Address	<3F8h>*1 <2F8h>*2 <3E8h> <2E8h> <338h> <228h> <220h> <238h>	System I/O base resources *1 UART port 1 *2 UART port 2
Interrupt	<IRQ3>*2 <IRQ4>*1 <IRQ6> <IRQ7> <IRQ11>	System interrupt resources *1 UART port 1 *2 UART port 2
Peripheral Type	<RS232>* <RS422> <RS485 FULL DUPLEX> <RS485 HALF DUPLEX>	Choose Port Mode RS232 RS422 RS485 Full Duplex RS485 Half Duplex
128 Bytes FIFO	<Disabled>* <Enabled>	128 bytes TX and RX FIFO

Tab. 19: UART Port 1/2 configuration

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.4.8 NVMe Information

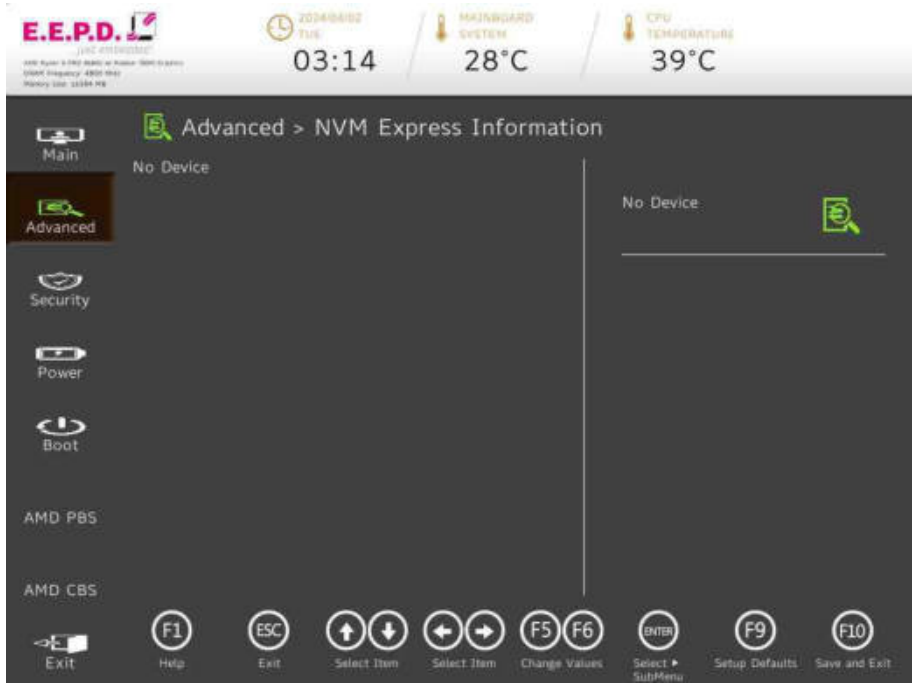


Fig. 62: NVMe information

BIOS Settings	Options	Description
NVMe Information	Info page	This function shows the connected NVMe devices.

Tab. 20: NVMe information

6.5 AMD CBS

Fig. 63: AMD CBS

BIOS Settings	Options	Description
CPU Common Options	See submenu	CPU Common Options
NBIO Common Options	See submenu	NBIO Common Options
FCH Common Options	See submenu	FCH Common Options
SMU Common Options	See submenu	SMU Common Options
SOC Miscellaneous Control	See submenu	SOC Miscellaneous Control

Tab. 21: AMD CBS

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.5.1 CPU Common Options

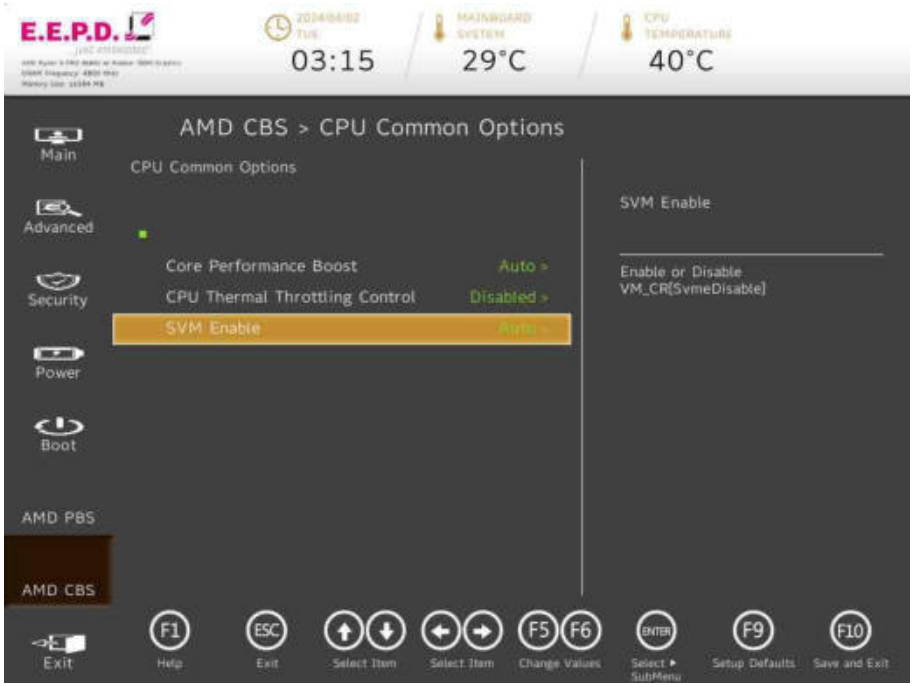


Fig. 64: CPU common options

BIOS Settings	Options	Description
Core Performance Boost	<Disabled> <Auto>*	This allows the processor to dynamically adjust and control the processor operating frequency to enable performance improvement, provided the processor has sufficient power and is within temperature specifications.
CPU Thermal Throttling Control	<Disabled>* <Enabled>	CPU Thermal Throttling Enable/Disable
SVM Enable	<Enabled> <Disabled> <Auto>*	Enable or disable the secure virtual machine

Tab. 22: CPU common options

6.5.2 NBIO Common Options

Fig. 65: NBIO common options

BIOS Settings	Options	Description
GFX Configurations	See submenu	GFX Configuration

Tab. 23: NBIO common options

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.5.2.1 GFX Configurations

Fig. 66: GFX configurations

BIOS Settings	Options	Description
iGPU Configuration	<UMA_SPECIFIED>* <UMA_AUTO>	UMA Mode. Select UMA_SPECIFIED to set UMA Frame Buffer Size.
UMA Version	<Legacy> <Non-Legacy> <Auto>*	UMA Legacy Version UMA Non-Legacy Version Hybrid Secure
UMA Frame Buffer Size	<Auto> <512M> <768M> <1G> <2G>* <3G> <4G> <8G> <16G>	This allows the system to manage the amount of shared memory for graphics. For systems equipped with 8GB of RAM or more, set the UMA buffer size to 1GB or 2GB.
GPU Host Translation Cache	<Disabled> <Enabled> <Auto>*	Option to disable GPU Host Translation Cache

Tab. 24: GFX configurations

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.5.3 FCH Common Options

Fig. 67: FCH common options

BIOS Settings	Options	Description
Ac Power Loss Options	See submenu	Ac Power Loss Options

Tab. 25: FCH common options

6.5.4 Ac Power Loss Options

Fig. 68: Ac power loss options

BIOS Settings	Options	Description
Ac Loss Control	<Always Off> <Always On>* <Previous>	This function allows you to set the power status after a power failure. Select [Always Off] to keep the system power off after a power failure. Select [Always On] to turn the system power after a power failure. Select [Previous] to allow the system to resume its last power state before a power failure.

Tab. 26: Ac power loss options

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.5.5 SMU Common Options

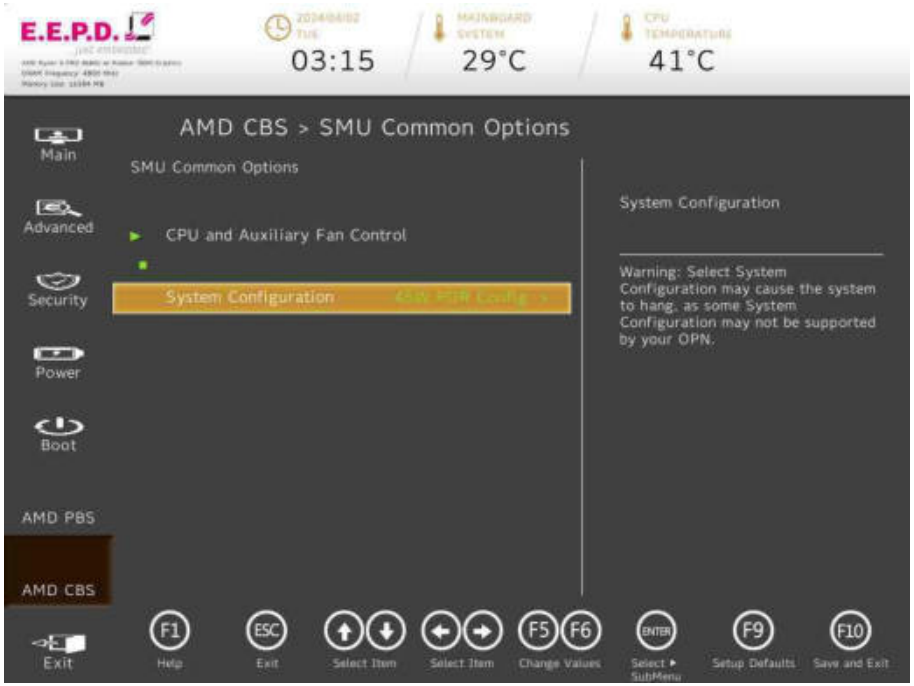


Fig. 69: SMU common options

BIOS Settings	Options	Description
CPU and Auxiliary Fan Control	See submenu	CPU and Auxiliary Fan Control
System Configuration	<15W-54W POR Configuration> (depending on the system)	Warning: Select System Configuration may cause the system to hang, as some System Configuration may not be supported by your OPN.

Tab. 27: SMU common options

6.5.5.1 CPU and Auxiliary Fan Control

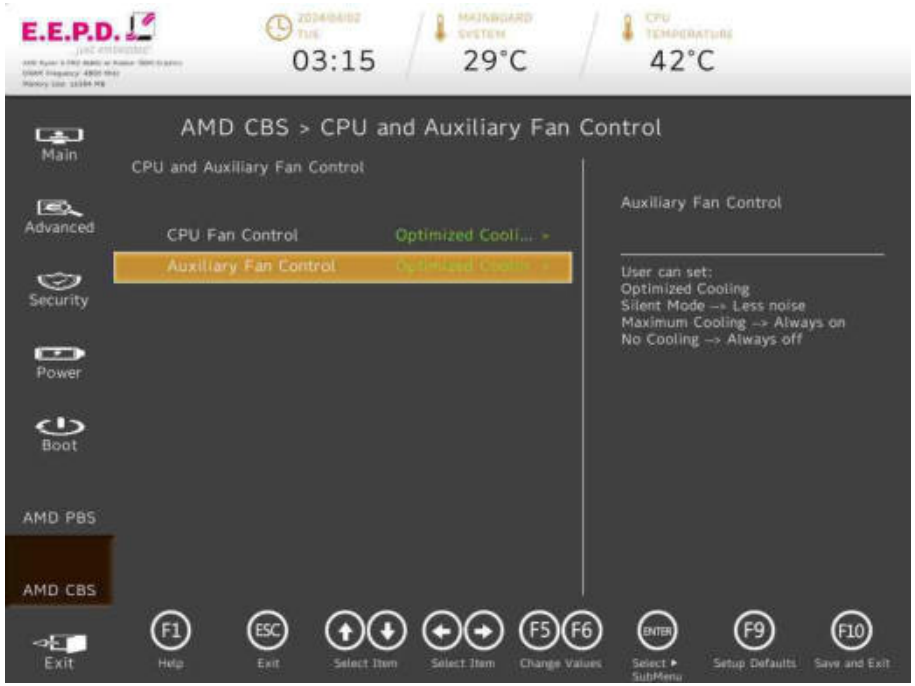


Fig. 70: CPU and auxiliary fan control

BIOS Settings	Options	Description
CPU Fan Control	<Optimized Cooling>* <Silent Mode> <Maximum Cooling> <No Cooling>	Optimized Cooling → Automatic PWM control depending on temperature Silent Mode → Less noise (30%) Maximum Cooling → Always on (100%) No Cooling → Always off
Auxiliary Fan Control		

Tab. 28: CPU and auxiliary fan control

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.5.6 SOC Miscellaneous Control

Fig. 71: SOC miscellaneous control

BIOS Settings	Options	Description
Trusted Platform Module	<Auto> <Disabled> <Enable dTPM>* <Enable ASP fTPM> <Enable Pluton fTPM>	Enable/Disable TPM physical presence.
Pluton Security Processor	<Auto>* <Disabled> <Enabled>	This option is used to enable/disable Pluton Security Processor

BIOS Settings	Microsoft Security Levels
Options	<Customized>* <dTPM Level 1 without Pluton Security Processor> <dTPM Level 2 without Pluton Security Processor> <dTPM Level 3 without Pluton Security Processor> <Pluton fTPM Level 1> <Pluton fTPM Level 2> <Pluton fTPM Level 3> <dTPM Level 1 with Pluton Security Processor> <dTPM Level 2 with Pluton Security Processor> <dTPM Level 3 with Pluton Security Processor> <ASP fTPM Level 0> <ASP fTPM Level 1> <ASP fTPM Level 2>
Description	This option provides one stop configuration for SCPC (Note: Firmware Anti-rollback is excluded). For Level 1, it will configure TPM, SVM, IOMMU, SecureBoot; For Level 2, it will configure TPM, SVM, IOMMU, DMAr, SecureBIO, SecureBoot; For Level 3, it will configure TPM, SMM Isolation, SVM, IOMMU, DMAr, TSME, SecureBIO, SecureBoot, Modern Standby. Regard TPM configuration, dTPM refers to discrete TPM. Pluton fTPM refers to Pluton firmware TPM. ASP fTPM refers to ASP firmware TPM. NOTE: FAR is required for Level3 and please enable it manually in CBS-> SOC Miscellaneous Control / Firmware Anti-rollback (FAR) / FAR Switch. dTPM with Pluton security processor is recommend configuration for Level1/2/3

Tab. 29: SOC miscellaneous control

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.6 AMD PBS Menu

Fig. 72: AMD PBS menu

BIOS Settings	Options	Description
AMD Firmware Version	See submenu	Show all of AMD Firmware Version
WWAN Power Control	<Enabled>* <Disabled>	Enable/disable Power of M.2 Key B Slot (WWAN)
WWAN Radio Operation	<Enabled>* <Disabled>	Enable/disable Radio operation of M.2 Key B Slot (WWAN)
WLAN Radio Operation	<Enabled>* <Disabled>	Enable/disable WLAN radio operation of M.2 Key E Slot
BT Radio Operation	<Enabled>* <Disabled>	Enable/disable Bluetooth (BT) radio operation of M.2 Key E Slot

Tab. 30: AMD PBS menu

6.6.1 AMD Firmware Version

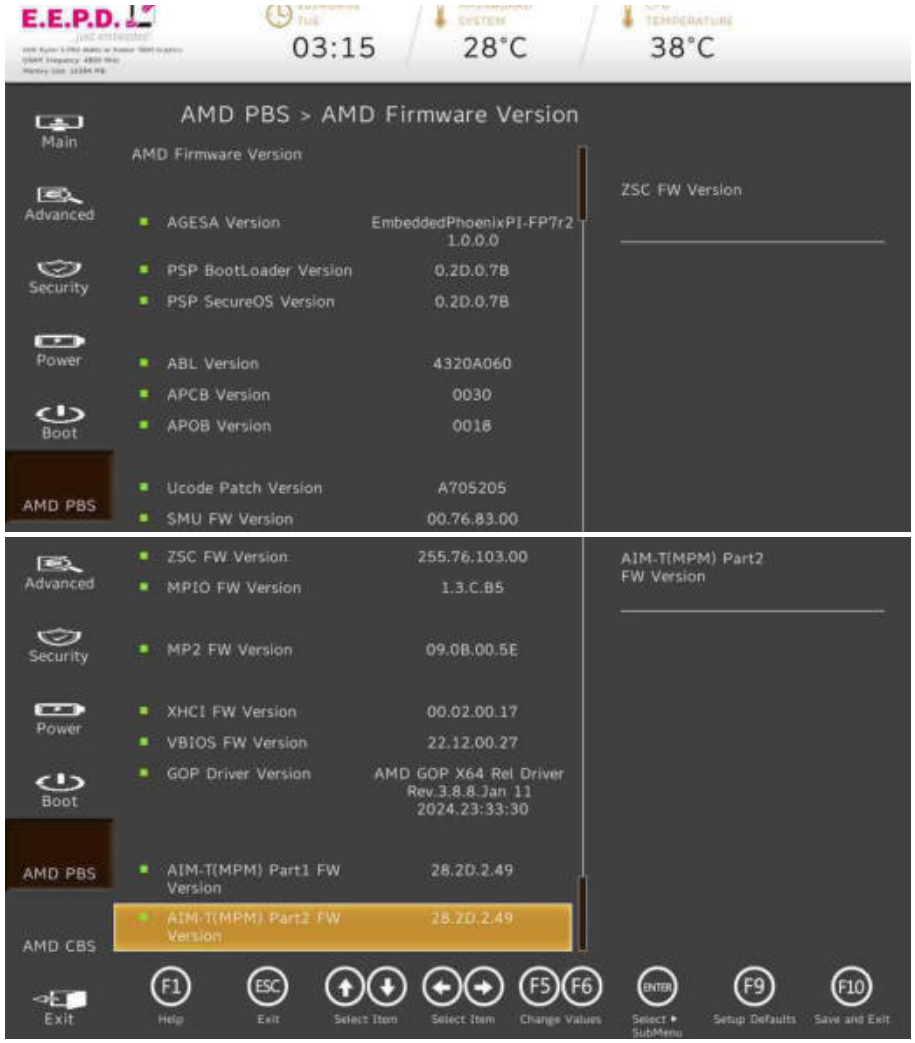


Fig. 73: AMD firmware version

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.7 Boot Menu

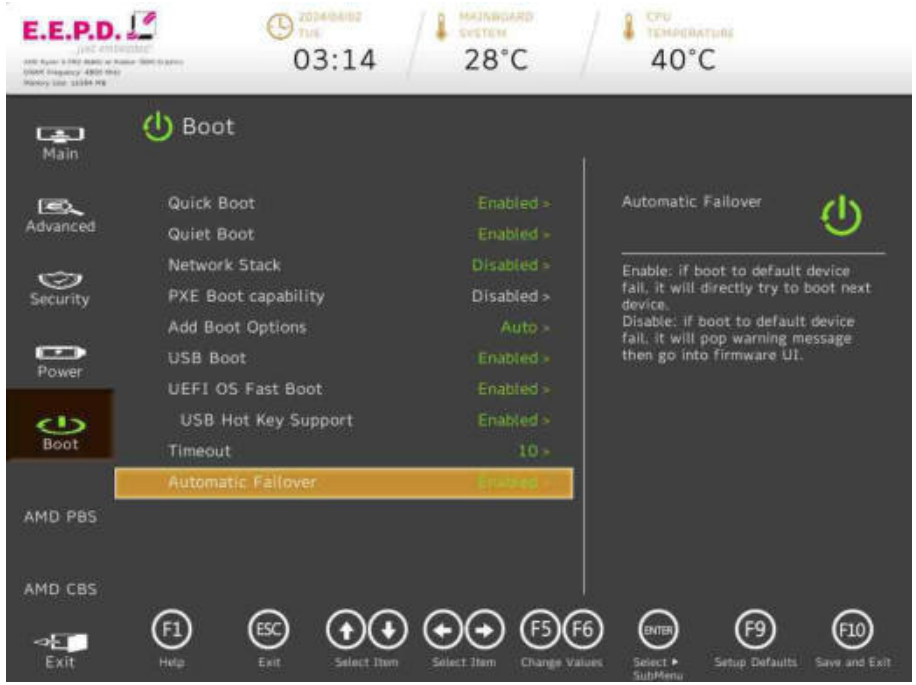


Fig. 74: Boot menu

BIOS Settings	Options	Description
Quick Boot	<Enabled>* <Disabled>	Allows InsydeH2O to skip certain tests while booting. This will decrease the time needed to boot the system.
Quiet Boot	<Enabled>* <Disabled>	Disables or enables booting in Text Mode.
Network Stack	<Disabled>* <Enabled>	Network Stack Support: UEFI IPv4/IPv6 PXE Legacy PXE OPROM
PXE Boot capability	<Disabled>*	Disabled: Support Network Stack UEFI PXE: IPv4/IPv6 Legacy: Legacy PXE OPROM only
Add Boot Options	<First> <Last> <Auto>*	Position in Boot Order for Shell, Network and Removables
USB Boot	<Enabled>* <Disabled>	Disables or enables booting to USB boot devices.
UEFI OS Fast Boot	<Enabled>* <Disabled>	If enabled the system firmware does not initialize keyboard and check for firmware menu key.
USB Hot Key Support	<Disabled> <Enabled>*	Enable/Disable to support USB hot key while booting. This will decrease the time needed to boot the system.
Timeout	Adjust value [0-10] Default value [10]*	The number of seconds that the firmware will wait before booting the original default boot selection.
Automatic Failover	<Disabled> <Enabled>*	Enable: if boot to default device fail, it will directly try to boot next device. Disable: if boot to default device fail, it will pop warning message then go into firmware UI.

Tab. 31: Boot menu

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.8 Power Menu

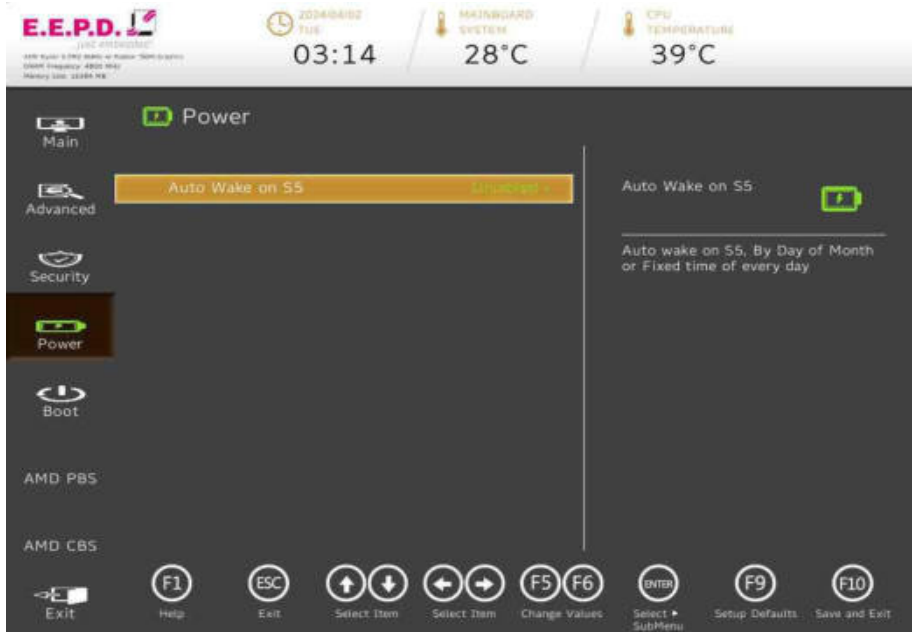


Fig. 75: Power menu

BIOS Settings	Options	Description
Auto Wake on S5	<Disabled>* <By Every Day> <By Day of Month>	Auto wake on S5, By Day of Month or Fixed time of every day

Tab. 32: Power menu

6.9 Exit Menu

Fig. 76: Exit menu

BIOS Settings	Options	Description
Exit Saving Changes		Exit system setup after saving your changes.
Save Change Without Exit		Save your changes without exiting system.
Exit Discarding Changes		Exit system setup without saving your changes.
Load Optimal Defaults		Load Optimal Defaults to all the setup options.
Save Custom Defaults		Save changes done so far as Custom Defaults.
Discard Changes		Discard changes done so far to any of the setup options.

Tab. 33: Exit menu

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.10 Security Menu

Fig. 77: Security menu

BIOS Settings	Options	Description
Current TPM Device	<Not Detected> <TPM 2.0 (AMD)> <TPM 2.0 (MSFT)> <TPM 2.0 (IFX)>*	Current TPM Device: TPM1.2, or TPM2.0. Go to *SoC Misc. Control* to select TPM device (*6.5.6)*
TrEE Protocol Version	<1.0> <1.1>*	TrEE Protocol Version: 1.0 or 1.1
TPM Availability	<Available>* <Hidden>	When hidden, don’t expose TPM to OS Warning: If Supervisor/User password is verified with TPM, change this option will disable password automatically
TPM Operation	<No Operation>* <Enable> <SetPCRBanks(Algorithm)> <LogAllDigests> <SetPPRequiredForClear_True> <SetPPRequiredForClear_False> <SetPPRequiredForTurnOn_False> <SetPPRequiredForTurnOn_True> <SetPPRequiredForTurnOff_False> <SetPPRequiredForTurnOff_True> <SetPPRequiredForChangePCRs_False> <SetPPRequiredForChangePCRs_True> <SetPPRequiredForChangeEPS_False> <SetPPRequiredForChangeEPS_True> <ChangeEPS>	Select one of the supported operations to change TPM2 state.
Clear TPM	[…] [X]	Clear TPM. Removes all TPM context associated with a specific Owner.
Set Supervisor Password	None	Install or change the password and the length of password must be greater than one character.

Tab. 34: Security menu

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

6.10.1 Storage Password Setup Page

Fig. 78: Storage password setup page

BIOS Settings	Options	Description
TCG Storage Action	<No Operation>* <Enable_BlockSIDFunc> <Disable_BlockSIDFunc> <PPRequiredForEnableBlockSID_True> <PPRequiredForEnableBlockSID_False> <PPRequiredForDisableBlockSID_True> <PPRequiredForDisableBlockSID_False>	Change BlockSID actions, includes enable or disable BlockSID, Require or not require physical presence when remote enable or disable BlockSID

Tab. 35: Storage password setup page

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Index of Figures

Fig. 1: NUCU with additional memory cooling 10
Fig. 2: NUCU with additional memory and SSD cooling 10
Fig. 3: System overview 11
Fig. 4: Top view 12
Fig. 5: Bottom view 12
Fig. 6: Side view 12
Fig. 7: Front view 13
Fig. 8: Recommended cutouts front panel, values [mm] 13
Fig. 9: Rear view 13
Fig. 10: Recommended cutouts rear panel, values [mm] 13
Fig. 11: Dimensions top side, values [mm] 14
Fig. 12: Dimensions front side, values [mm] 14
Fig. 13: Dimensions top side with additional cooling, values [mm] 14
Fig. 14: Dimensions front side with additional cooling, values [mm] 14
Fig. 15: Connection overview top side 16
Fig. 16: Connection overview bottom side 17
Fig. 17: Connection overview side 17
Fig. 18: Mini-DP++ connectors detail 18
Fig. 19: Mini-DP++ connector schematic 18
Fig. 20: Ethernet Dual-port detail 18
Fig. 21: Ethernet port schematic 18
Fig. 22: Dual-USB-A 3.2 port detail 19
Fig. 23: USB-A 3.2 port schematic 19
Fig. 24: USB-C ports detail 19
Fig. 25: USB-C port schematic 19
Fig. 26: Molex USB internal connector detail 20
Fig. 27: Molex USB internal connector schematic 20
Fig. 28: DDR5 SO-DIMM sockets detail 20
Fig. 29: RAM assembly 20
Fig. 30: Power connector detail 21
Fig. 31: Power connector schematic 21
Fig. 32: M.2 Key M connector detail 22
Fig. 33: M.2 Key E connector detail 22
Fig. 34: M.2 Key B connector detail 22
Fig. 35: M.2 module assembly example 22
Fig. 36: M.2 module assembly angle 22
Fig. 37: OCuLink connector detail 23
Fig. 38: Audio Jack detail 23
Fig. 39: Molex feature connector detail 23
Fig. 40: Molex feature connector schematic 23
Fig. 41: Molex RS232/485 connector detail 24
Fig. 42: Molex RS232/485 connector schematic 24
Fig. 43: Molex battery connector detail 24
Fig. 44: Molex battery connector schematic 24
Fig. 45: Molex CPU FAN connector detail 25
Fig. 46: Molex auxiliary FAN connector detail 25
Fig. 47: Molex FAN connector schematic 25
Fig. 48: Power Button/Power and SSD Activity LEDs detail 26
Fig. 49: Molex power button connector detail 26
Fig. 50: Molex power button connector schematic 26
Fig. 51: Main menu 28
Fig. 52: Advanced menu 29
Fig. 53: Boot configuration 30
Fig. 54: Peripheral configuration 30
Fig. 55: USB configuration 31
Fig. 56: USB ports 31
Fig. 57: Chipset configuration 32
Fig. 58: ACPI table 32
Fig. 59: NUCU options 33
Fig. 60: SIO NCT6126D 34
Fig. 61: UART port 1/2 configuration 35
Fig. 62: NVMe information 36
Fig. 63: AMD CBS 36
Fig. 64: CPU common options 37
Fig. 65: NBIO common options 37

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Fig. 66: GFX configurations 38
Fig. 67: FCH common options 39
Fig. 68: Ac power loss options 39
Fig. 69: SMU common options 40
Fig. 70: CPU and auxiliary fan control 40
Fig. 71: SOC miscellaneous control 41
Fig. 72: AMD PBS menu 42
Fig. 73: AMD firmware version 42
Fig. 74: Boot menu 43
Fig. 75: Power menu 44
Fig. 76: Exit menu 44
Fig. 77: Security menu 45
Fig. 78: Storage password setup page 46

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Index of Tables

Tab. 1: Voltage overview 15
Tab. 2: USB internal connector 20
Tab. 3: Power connector 21
Tab. 4: Feature connector 23
Tab. 5: RS232/485 connector 24
Tab. 6: Battery connector 24
Tab. 7: FAN connectors 25
Tab. 8: Power button connector 26
Tab. 9: Main menu 28
Tab. 10: Advanced menu 29
Tab. 11: Boot configuration 30
Tab. 12: Peripheral configuration 30
Tab. 13: USB configuration 31
Tab. 14: USB ports 31
Tab. 15: Chipset configuration 32
Tab. 16: ACPI table 32
Tab. 17: NUCU options 33
Tab. 18: SIO NCT6126D 34
Tab. 19: UART Port 1/2 configuration 35
Tab. 20: NVMe information 36
Tab. 21: AMD CBS 36
Tab. 22: CPU common options 37
Tab. 23: NBIO common options 37
Tab. 24: GFX configurations 38
Tab. 25: FCH common options 39
Tab. 26: Ac power loss options 39
Tab. 27: SMU common options 40
Tab. 28: CPU and auxiliary fan control 40
Tab. 29: SOC miscellaneous control 41
Tab. 30: AMD PBS menu 42
Tab. 31: Boot menu 43
Tab. 32: Power menu 44
Tab. 33: Exit menu 44
Tab. 34: Security menu 45
Tab. 35: Storage password setup page 46

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Terminology

BT	Bluetooth
CPU	Central Processing Unit or processor
DC	Direct Current
DDR5	Fifth generation „Double Data Rate” memory technology
DP	Display port
ECC	Error Correcting Code
2.5 Gigabit Ethernet	Ethernet connection with a frame transfer speed up to 2500 Mbit/s
GND	Ground
MIC	Microphone
M.2	Next generation mSATA
OCP	Over Current Protection
PWM	Pulse-Width Modulation
RAM	Random Access Memory
RS-232	Serial standard interface
RS-485	Serial standard interface
SoC	System on a Chip means the integration of all or a large part of the functions of a programmable electronic system on a single chip
SO-DIMM	Small Outline Dual Inline Memory Module
SSD	Solid State Drive
USB	Universal Serial Bus
Watchdog	A watchdog (timer) is a computer hardware timing device that triggers a system reset if the main program hangs, in order to keep the computer running
WLAN	Wireless Local Area Network
WWAN	Wireless Wide Area Network

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

Classified Index

–A–

Advanced Menu 29
AMD CBS 36
AMD PBS Menu 42
Assembly 12
Audio Jack 23

–B–

Battery Connector 24
Boot Menu 43

–C–

Connection Overview 16

–D–

DDR5 SO-DIMM Sockets 20
Dimensions 14
Dual-USB 3.2 Ports 19

–E–

Entering Setup 27
Environmental Specification 10
Exit Menu 44

–F–

FAN Connectors 25
Feature Connector 23
Feature Details 15
Feature Overview 8

–G–

Gigabit Ethernet Ports 18

–M–

M.2 Sockets 22
Main Menu 28
Mini-DP++ Connectors 18
Most Common Settings 27

–N–

NUCU options 33

–O–

OCuLink Connector 23

–P–

Power Button Connector 26
Power Button, Power and SATA/SSD Act. LEDs 26
Power Connector 21
Power Menu 44
Product Views 12

–R–

RS232/485 Connector 24

–S–

Security Menu 45
System Overview 11

–U–

USB 2.0 Connectors 20
USB4 Ports 19

Copyright © 2026 E.E.P.D. GmbH. All rights reserved.

E.E.P.D. GmbH | Gewerbering 3 | 85258 Weichs

Copyright © E.E.P.D. GmbH. All rights reserved.

E.E.P.D.
...just embedded!